FusionServer 2298 V5 Server

Technical White Paper

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About This Document

Purpose

This document describes the FusionServer 2298 V5 rack server in terms of features, structure, specifications, and component hardware and software compatibility.

Intended Audience

This document is intended for pre-sales engineers.

Symbol Conventions

The symbols that may be found in this document are defined as follows.

Symbol	Description
DANGER	Indicates a hazard with a high level of risk which, if not avoided, will result in death or serious injury.
WARNING	Indicates a hazard with a medium level of risk which, if not avoided, could result in death or serious injury.
CAUTION	Indicates a hazard with a low level of risk which, if not avoided, could result in minor or moderate injury.
NOTICE	Indicates a potentially hazardous situation which, if not avoided, could result in equipment damage, data loss, performance deterioration, or unanticipated results. NOTICE is used to address practices not related to personal injury.
NOTE	Supplements the important information in the main text. NOTE is used to address information not related to personal injury, equipment damage, and environment deterioration.

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Change History

Issue	Date	Description
07	2024-03-29	Updated **6.1 Technical Specifications**.
06	2023-11-30	• Updated **10 Certifications**. • Added **11 Waste Product Recycling**. • Updated **A.4 Nameplate** .
05	2023-08-31	Updated **5.8 PSUs** .
04	2022-11-11	• Updated **4 Logical Structure**. • Updated **6.3 Physical Specifications** . • Updated **8.1 Security**.
03	2022-06-25	• Added a figure that shows how to measure dimensions. • Updated the physical structure diagram and added the PSU backplane information. • Updated **5.5.1 Drive Configuration**. • Added **5.10.3 PSU Backplane** . • Updated **6.1 Technical Specifications** and claimed support for U.2 drives. • Updated CE, UKCA, and CCC certification standards in **10 Certifications**. • Added **A.1 Chassis Label**.
02	2022-03-18	Added **Certifications [2298 V5-BP]**.
01	2021-12-20	This issue is the first official release.

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1 Product Introduction

FusionServer 2298 V5 (2298 V5) is a new-generation 2U 2-socket rack server designed for Internet, enterprise, and telecom applications.

The 2298 V5 applies to distributed storage, big data analysis, software-defined storage, video, backup and archiving, and other storage-intensive cold storage scenarios. It delivers unmatched flexibility and expandability of local storage, reduced storage costs, as well as high computing performance.

The 2298 V5 features ultra-high density, superb performance, easy O&M, and high expandability.

NOTE

For details about the 2298 V5 nameplate information, see **A.4 Nameplate** .

Figure 1-1 2298 V5

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2 Features

Performance and Scalability

- Powered by two Intel® Xeon® Scalable Skylake or Cascade Lake processors, the server provides up to 28 cores, 3.8 GHz frequency, a 38.5 MB L3 cache, and two 10.4 GT/s UPI links between the processors, which deliver supreme processing performance.
  - It supports up to two processors with 56 cores and 112 threads to maximize the concurrent execution of multithreaded applications.
  - An L2 cache is added. Each core can exclusively use 1 MB of L2 cache and at least 1.375 MB of L3 cache.
  - Intel Turbo Boost Technology 2.0 allows processor cores to run faster than the frequency specified in the Thermal Design Power (TDP) configuration if they are operating below power, current, and temperature specification limits.
  - Intel Hyper-Threading Technology enables each processor core to run up to two threads, improving parallel computation capability.
  - The hardware-assisted Intel® Virtualization Technology (Intel® VT) allows operating system (OS) vendors to better use hardware to address virtualization workloads.
  - Intel® Advanced Vector Extensions 512 (Intel AVX-512) significantly accelerates floating-point performance for computing-intensive applications.
  - The Cascade Lake processors support Intel® Deep Learning Boost vector neural network instructions (VNNI) to improve the performance of deep learning applications.
- The server supports double data rate 4 (DDR4) registered dual in-line memory modules (RDIMMs) and load-reduced DIMMs (LRDIMMs) with error checking and correcting (ECC). A server fully configured with twelve 2933 MT/s memory modules (only available with Cascade Lake processors) provides 768 GB memory space and the maximum theoretical memory bandwidth of 274.96875 GB/s.
- Flexible drive configurations cater to a variety of business requirements and ensure high elasticity and scalability of storage resources.
- SATA/SAS SSDs or NVMe drives can be used as the cache to improve drive performance.

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- The LANs on motherboard (LOMs) and Open Compute Project (OCP) 2.0 mezzanine cards provide a variety of ports to meet different networking requirements.
- The server supports up to four PCIe 3.0 slots.
- With Intel integrated I/O, the Intel® Xeon® Scalable processors integrate the PCIe 3.0 controller to shortens I/O latency and improve overall system performance.

Availability and Serviceability

- Carrier-class components with process expertise ensure high system reliability and availability.
- The server supports twenty-four 3.5-inch front SAS/SATA drives and four 2.5-inch rear SAS/SATA/NVMe drives. All the drives are hot-swappable, and the 2.5-inch SAS/SATA drives support RAID1, 10, and 1E.
- The SSDs offer better reliability than HDDs, ensuring continued system performance.
- The server provides simplified O&M and efficient troubleshooting through the UID/HLY LED indicators on the front panel and iBMC WebUI.
- The iBMC monitors system parameters in real time, triggers alarms, and performs recovery actions in case of failures, minimizing system downtime.
- For more information about the warranty in the Chinese market, see **Warranty**.

Manageability and Security

- The built-in iBMC monitors server operating status and provides remote management.
- A password is required for accessing the BIOS, ensuring system boot and management security.
- The Network Controller Sideband Interface (NC-SI) allows a network port to serve as a management port and a service port for maximized return on investment (ROI) for customers. The NC-SI feature is disabled by default and can be enabled through the iBMC or BIOS.
- The integrated Unified Extensible Firmware Interface (UEFI) improves setup, configuration, and update efficiency and simplifies fault handling.
- The Advanced Encryption Standard–New Instruction (AES NI) algorithm allows faster and stronger encryption.
- Intel Execute Disable Bit (EDB) function prevents certain types of malicious buffer overflow attacks when working with a supported OS.
- Intel Trusted Execution Technology enhances security using hardware-based defense against malicious software attacks, allowing applications to run independently.
- The trusted platform module (TPM) and trusted cryptography module (TCM) provide advanced encryption functions, such as digital signatures and remote authentication.

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NOTE

The service port with NC-SI enabled supports the following configuration:

- Configuring any port on the LOM, OCP 2.0 mezzanine card 1, or PCIe NIC as the service port with NC-SI enabled. Host port 1 is configured by default.
- Enabling, disabling, and setting a virtual local area network (VLAN) ID for this port. The VLAN ID is **0** and disabled by default.
- Configuring IPv4 addresses (IPv4 address, subnet mask, and gateway) and IPv6 addresses (IPv6 address, prefix length, and gateway) for this port.

Energy Efficiency

- The 80 Plus Platinum power supply units (PSUs) of multiple power ratings provide 94% power efficiency at 50% load.
- The server supports active/standby power supplies and high-voltage DC (HVDC) for improved power supply efficiency.
- Efficient voltage regulator-down (VRD) power supplies for boards minimize the energy loss from DC/DC power conversion.
- Area-based, Proportional-Integral-Derivative (PID) intelligent fan speed adjustment and intelligent CPU frequency scaling optimize heat dissipation and reduce overall system power consumption.
- The improved thermal design with energy-efficient fans ensures optimal heat dissipation and reduces system power consumption.
- The server is protected with power capping and power control measures.
- Staggered spin-up for drives reduces the server boot power consumption.
- Intel® Intelligent Power Capability allows a processor to be powered on or off based on requirements.
- Low-voltage Intel® Xeon® Scalable processors consume less energy, ideally suited for data centers and telecommunications environments constrained by power and thermal limitations.
- SSDs consume 80% less power than HDDs.

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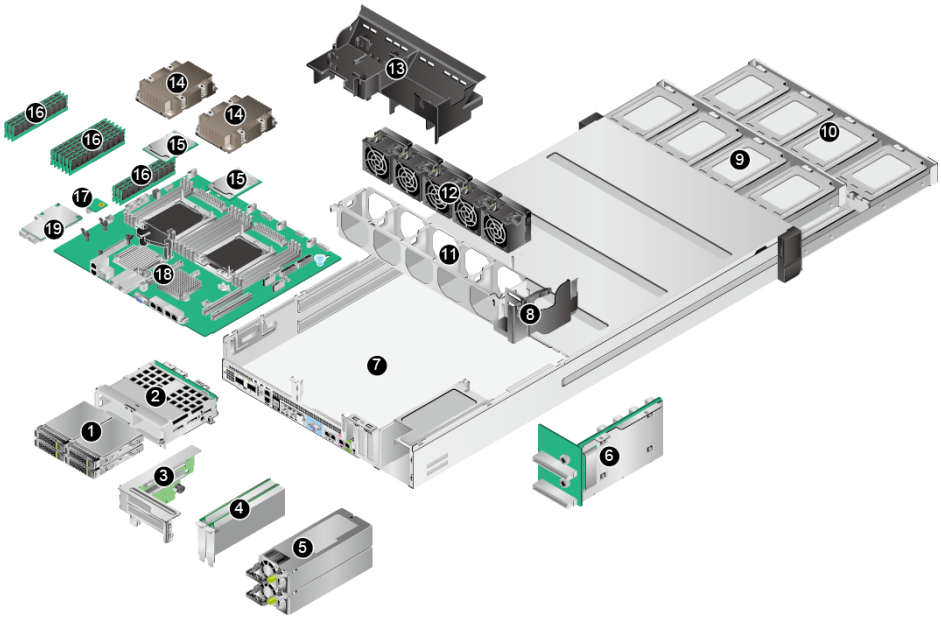
3 Physical Structure

Figure 3-1 2298 V5 physical structure



1	Rear drive	2	Rear-drive module
3	PCIe riser module	4	Standard PCIe card
5	PSU	6	PSU backplane
7	Chassis	8	Air duct 1
9	Upper-layer drive drawer	10	Lower-layer drive drawer
11	Fan module bracket	12	Fan module
13	Air duct 2	14	Heat sink
15	Processor	16	DIMM
17	TPM/TCM	18	Mainboard

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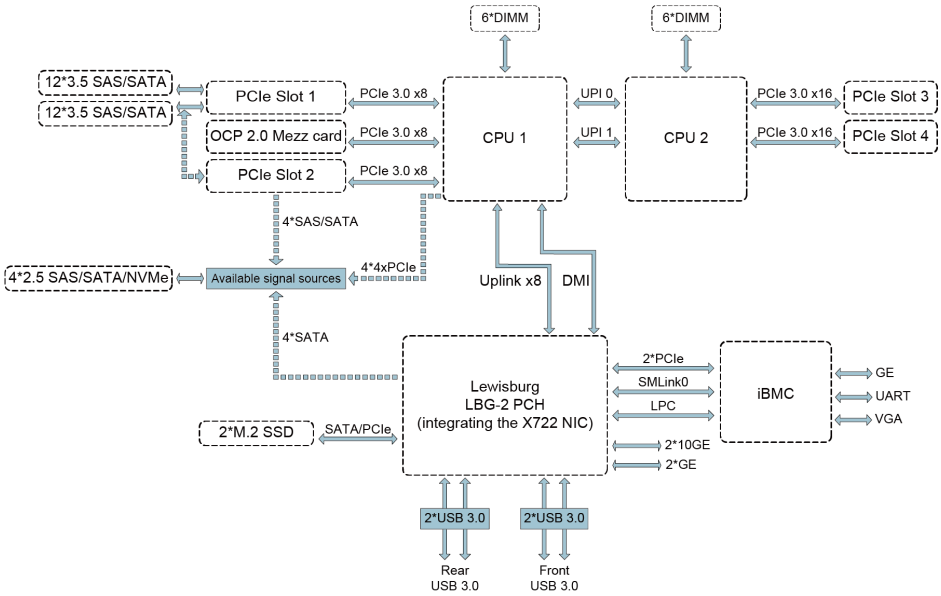
19	OCP 2.0 Mezz card	-	-

4 Logical Structure

Figure 4-1 2298 V5 logical structure



- The server supports one or two Intel® Xeon® Scalable processors.
- The server supports up to 12 memory modules.
- The CPUs (processors) interconnect with each other through two UPI links at a speed of up to 10.4 GT/s.
- The CPUs are directly connected to five PCIe slots:
  - CPU 1 is connected to two full-height half-length (FHHL) PCIe 3.0 x8 cards and one PCIe 3.0 x8 OCP 2.0 mezzanine card.
  - CPU 2 is connected to two half-height half-length (HHHL) PCIe 3.0 x16 cards.
- The server supports 24 front 3.5-inch SAS/SATA drives directly connected to a 24-port PCIe SAS HBA card.
- The server supports four rear 2.5-inch SAS/SATA/NVMe drives that can be directly connected to the following signal sources:
  - PCIe RAID controller card when SAS/SATA drives are configured
  - PCH SATA interface when SATA drives are configured

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  - CPU PCIe interface when NVMe drives are configured
- The LBG-2 Platform Controller Hub (PCH) supports:
  - Two 10GE optical LOM ports
  - Two GE electrical LOM ports
  - Two SATA or PCIe ports for M.2 SSDs
- Uses the BMC management chip, and supports a VGA, a management network port, a debugging serial port, and other management ports.

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5 Hardware Description

5.1 Front Panel
5.2 Rear Panel
5.3 Processor
5.4 Memory
5.5 Storage
5.6 Network
5.7 I/O Expansion
5.8 PSUs
5.9 Fans
5.10 Boards

5.1 Front Panel

5.1.1 Appearance

Figure 5-1 Front view

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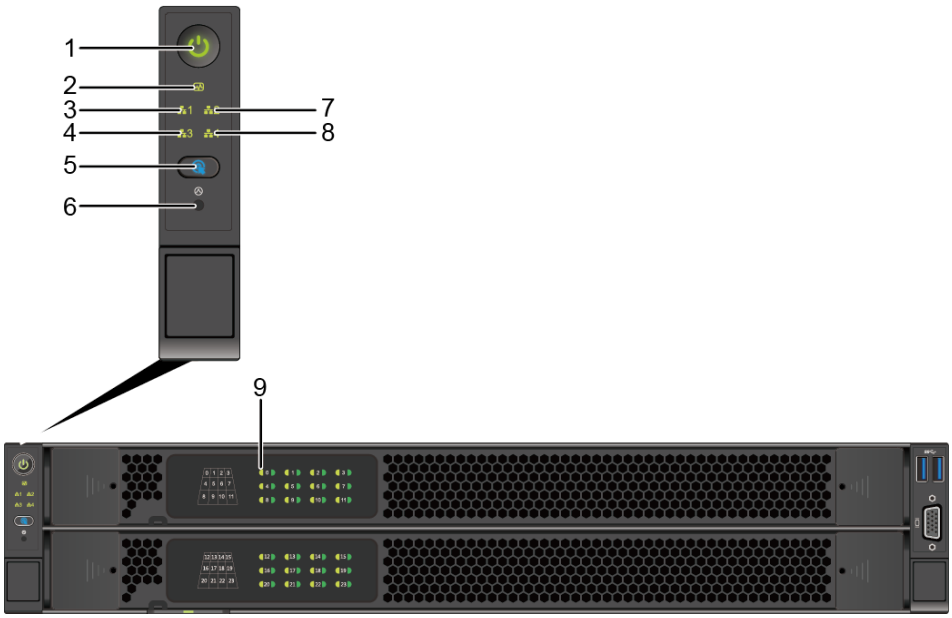
1	Drive drawer ejector lever	2	Drive drawer ejector release slider
3	Upper drive drawer (Slot 1)	4	Mounting ear ejector lever
5	Lower drive drawer (Slot 2)	6	Slide-out label plate (with an SN label)

5.1.2 Indicators and Buttons

Indicator and Button Positions

Figure 5-2 Indicators and buttons on the front panel



1	Power button/indicator	2	Health status indicator
3	10GE optical port (LOM port 1) connection status indicator	4	GE electrical port (LOM port 3) connection status indicator
5	UID button/indicator	6	Non-Maskable Interrupt (NMI) button
7	10GE optical port (LOM port 2) connection status indicator	8	GE electrical port (LOM port 4) connection status indicator
9	Status indicators of the drives in the front drawers	-	-

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Indicator and Button Descriptions

Table 5-1 Description of indicators and buttons on the front panel

Sign	Indicator and Button	Description
	Power button/ indicator	Power indicator: ● Off: The device is not powered on. ● Steady green: The device is powered on. ● Blinking yellow: The iBMC is starting. The power button is locked and cannot be pressed. The iBMC is started in about 1 minute, and then the power indicator is steady yellow. ● Steady yellow: The device is standby. Power button: ● When the device is powered on, you can press this button to gracefully shut down the OS. **NOTE** For different OSs, you may need to shut down the OS as prompted. ● When the device is powered on, holding down this button for 6 seconds will forcibly power off the device. ● When the power indicator is steady yellow, you can press this button to power on the device.
	UID button/ indicator	The UID button/indicator helps identify and locate a device. UID indicator: ● Off: The device is not being located. ● Blinking or steady blue: The device is being located. UID button description: ● You can control the UID indicator status by pressing the UID button or using the iBMC. ● You can press this button to turn on or off the UID indicator. ● You can press and hold down this button for 4 to 6 seconds to reset the iBMC.

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Sign	Indicator and Button	Description
	Health status indicator	● Off: The device is powered off or is faulty. ● Blinking red at 1 Hz: A major alarm has been generated on the system. ● Blinking red at 5 Hz: A critical alarm has been generated on the system. ● Steady green: The device is operating properly.
	NMI button	A non-maskable interrupt (NMI) is generally triggered to stop the OS for debugging. To trigger an NMI, press this button or click the button on the iBMC WebUI. **NOTICE** ● Press the NMI button only when the OS is abnormal. Do not press this button when the server is operating properly. An NMI does not gracefully shut down the OS and causes service interruption and data loss. ● Before pressing the NMI button, ensure that the OS has the NMI processing program. Otherwise, the OS may crash. Exercise caution when pressing this button.
	LOM port connection status indicator	Each indicator shows the connection status of an Ethernet LOM port. ● Off: The network port is not in use or has failed. ● Steady green: The network port is properly connected. **NOTE** ● The indicators correspond to two 10GE and two GE network ports on the mainboard. ● The LOM has a standby power supply and will not be powered off even if the service system is powered off. As long as the LOM ports are properly connected to other working network devices, the network ports will remain connected and the indicators are on.
	Status indicators of the drives in the front drawers	Indicate the status of the drives in the front drive drawers. For details, see **Front Drive Drawer Indicators (3.5-inch SAS/SATA drives)**.

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5.1.3 Ports

Port Positions

Figure 5-3 Ports on the front panel

1	USB 3.0 ports	2	VGA port

Port Description

Table 5-2 Ports on the front panel

Port	Type	Quantity	Description
USB port	USB 3.0	2	Used to connect to a USB device. **NOTICE** Before connecting an external USB device, check that the USB device functions properly. The server may operate abnormally if an abnormal USB device is connected.
VGA port	DB15	1	Used to connect a display terminal, such as a monitor or KVM.

5.2 Rear Panel

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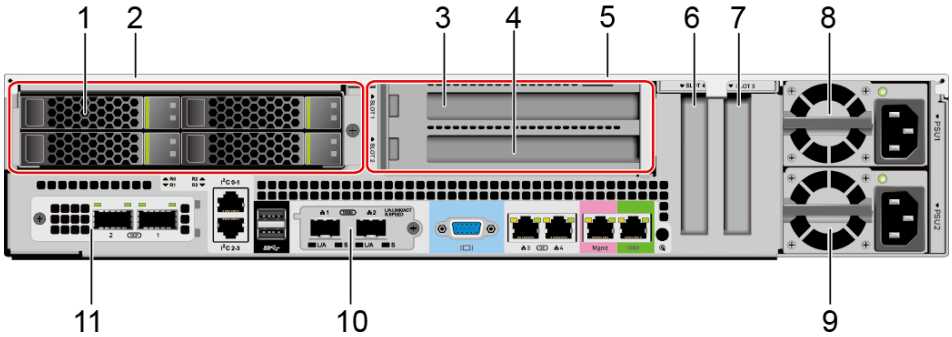
5.2.1 Appearance

Figure 5-4 Rear view



1	SAS/SATA/NVMe drives	2	Rear drive module
3	PCIe Slot1	4	PCIe Slot2
5	PCIe riser module	6	PCIe Slot4
7	PCIe Slot3	8	PSU 1
9	PSU 2	10	LOM
11	(Optional) OCP 2.0 mezzanine card	-	-

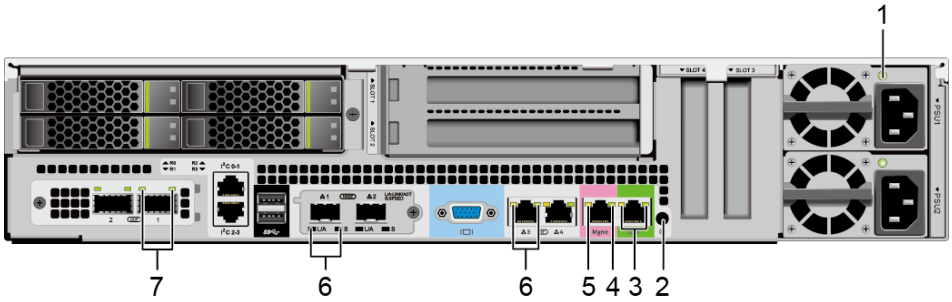
NOTE

- For details about the LOM and OCP 2.0 mezzanine card, see **5.6 Network**.
- The preceding figure is for reference only.

5.2.2 Indicators

Indicator Positions

Figure 5-5 Indicators on the rear panel



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1	PSU indicator	2	UID Indicator
3	Serial port indicators **NOTE** The indicators are reserved.	4	Connection status indicator of the management network port
5	Data transmission status indicator of the management network port	6	LOM indicators
7	OCP 2.0 mezzanine card indicator	-	-

Indicator Description

Table 5-3 Description of indicators on the rear panel

Indicator	Description
LOM indicators	For details, see **5.6.1 LOMs** .
OCP 2.0 mezzanine card indicator	For details, see **5.6.2 OCP 2.0 Mezzanine Cards**.
PSU indicator	● Off: No power is supplied. ● Blinking green at 1 Hz: – The input is normal, and the server is standby. – The input is overvoltage or undervoltage. – The PSU is in deep hibernation mode. ● Blinking green at 4 Hz: The firmware is being upgraded online. ● Steady green: The power input and output are normal. ● Steady orange: The input is normal, but no power output is supplied. **NOTE** The possible causes of no power output are as follows: ● Power supply overtemperature protection ● Power output overcurrent or short-circuit ● Output overvoltage ● Short-circuit protection ● Device failure (excluding failure of all devices)
UID Indicator	The UID indicator helps identify and locate a device. ● Off: The device is not being located. ● Blinking or steady blue: The device is being located. **NOTE** You can control the UID indicator state by pressing the UID button or running a command on the iBMC CLI.

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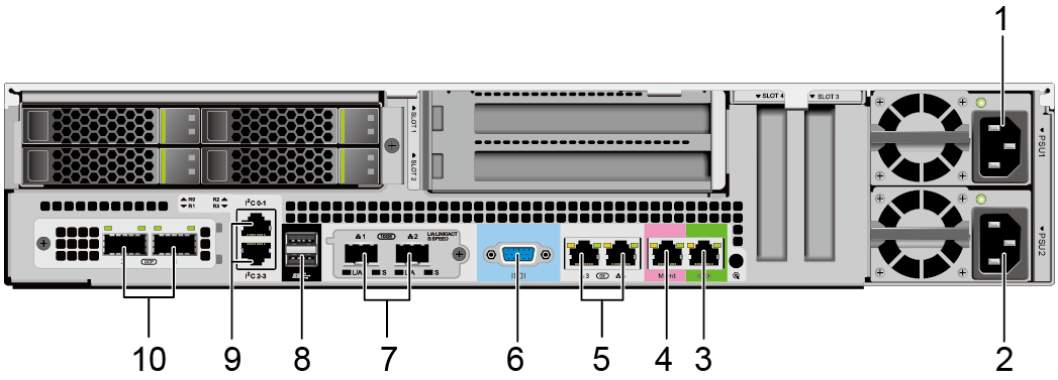
Indicator	Description
Connection status indicator of the management network port	• Off: The network port is not connected. • Steady green: The network port is properly connected.
Data transmission status indicator of the management network port	• Off: No data is being transmitted. • Blinking yellow: Data is being transmitted.

5.2.3 Ports

Port Positions

Figure 5-6 Ports on the rear panel



1	Socket for PSU 1	2	Socket for PSU 2
3	Serial port	4	Management network port
5	LOM port 2	6	VGA port
7	LOM port 1	8	USB 3.0 port
9	Reserved ports	10	OCP 2.0 mezzanine card port

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Port Description

Table 5-4 Description of ports on the rear panel

Tool	Type	Quantity	Description
LOM port 1	10GE optical port	2	For details, see **5.6.1 LOMs** .
LOM port 2	GE electrical port	2	For details, see **5.6.1 LOMs** .
OCP 2.0 mezzanine card port	-	-	For details, see **5.6.2 OCP 2.0 Mezzanine Cards**.
PSU socket	-	2	Used to connect to the power distribution unit (PDU) in the cabinet. You can select the number of power supply units (PSUs) as required. **NOTE** ● When determining the quantity of PSUs, ensure that the rated power of the PSUs is greater than that of the server. ● If only one PSU is used, **Predicted PSU Status** cannot be set to **Active/Standby** on the iBMC WebUI.
Serial port	RJ45	1	Default operating system serial port used for debugging. You can also set it as the iBMC serial port by using the iBMC command. **NOTE** The port uses 3-wire serial communication interface, and the default baud rate is 115,200 bit/s.
Management network port	1000BASE-T	1	Used for server management. **NOTE** ● The management network port is a GE port that supports 100 Mbit/s and 1000 Mbit/s auto-negotiation.
VGA port	DB15	1	Used to connect a display terminal, such as a monitor or KVM.

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Tool	Type	Quantity	Description
USB 3.0 port	USB 3.0	2	Used to connect to a USB device. **NOTICE** Before connecting an external USB device, check that the USB device functions properly. The server may operate abnormally if an abnormal USB device is connected.

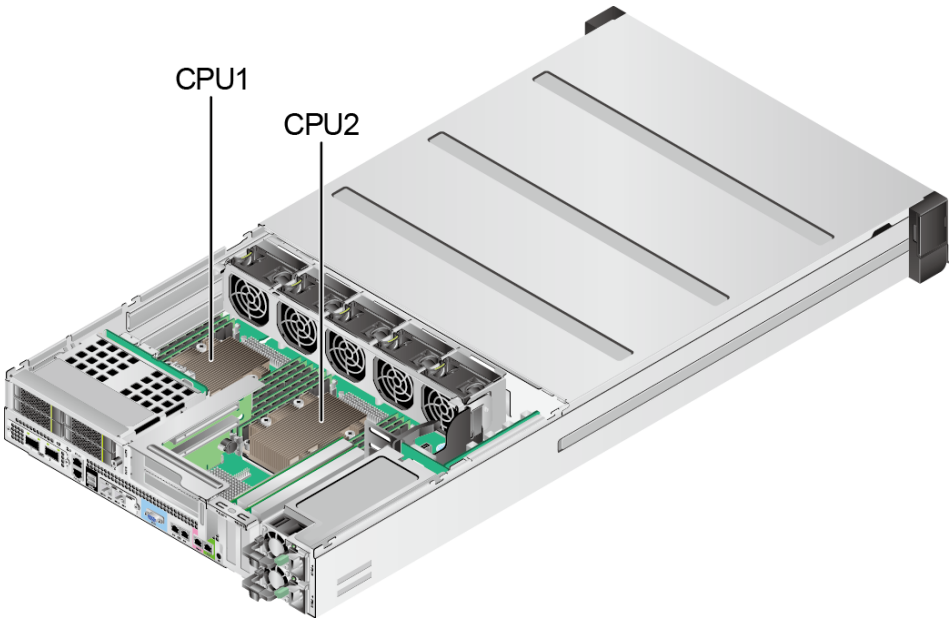
5.3 Processor

- The server supports one or two processors.
- If only one processor is required, install it in socket **CPU1**.
- The same model of processors must be used in a server.
- Contact your local sales representative or use the **Compatibility List** to determine the components to be used.

NOTICE

According to Intel's statement, the processors in overclocking mode may cause instantaneous thermal throttling on certain OSs. The thermal throttling, however, does not affect the processor performance and reliability.

Figure 5-7 Processor positions



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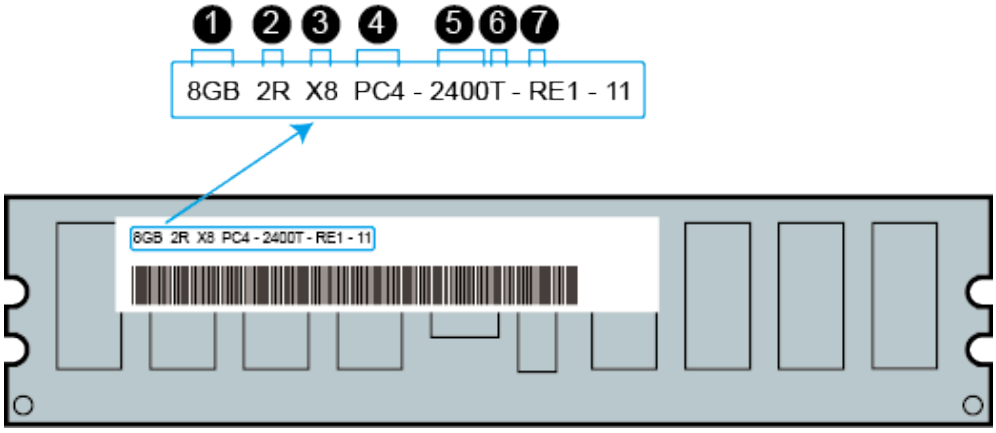
5.4 Memory

5.4.1 DDR4 Memory

5.4.1.1 Memory Identifier

You can determine the memory module properties based on the label attached to the memory module.

Figure 5-8 Memory identifier



Callout	Description	Definition
1	Capacity of the memory module	• 8 GB • 16 GB • 32 GB • 64 GB • 128 GB
2	Number of ranks of the memory module	• 1R: single-rank • 2R: dual-rank • 4R: quad-rank • 8R: octal-rank
3	Data width on the DRAM	• X4: 4-bit • X8: 8-bit
4	Type of the memory interface	• PC3: DDR3 • PC4: DDR4

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Callout	Description	Definition
5	Maximum memory speed	● 2133 MT/S ● 2400 MT/S ● 2666 MT/S ● 2933 MT/S ● 3200 MT/S
6	Column Access Strobe (CAS) latency	● P: 15 ● T: 17
7	DIMM type	● R: RDIMM ● L: LRDIMM

5.4.1.2 Memory Subsystem Architecture

The 2298 V5 provides 12 memory slots. Each processor integrates six memory channels.

Table 5-5 Memory channels

CPU	Memory Channel	Memory Slot
CPU 1	A	DIMM000(A)
	B	DIMM010(B)
	C	DIMM020(C)
	D	DIMM030(D)
	E	DIMM040(E)
	F	DIMM050(F)
CPU 2	G	DIMM100(G)
	H	DIMM110(H)
	I	DIMM120(I)
	J	DIMM130(J)
	K	DIMM140(K)
	L	DIMM150(L)

5.4.1.3 Memory Compatibility

Observe the following rules when configuring DDR4 DIMMs:

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NOTICE

- A server must use the same model of DDR4 DIMMs, and all the DIMMs operate at the same speed, which is the smallest value of:
  - Memory speed supported by a processor
  - Maximum operating speed of a DIMM
- The DDR4 DIMMs of different types (RDIMM and LRDIMM) and specifications (capacity, bit width, rank, and height) cannot be used together.
- Contact your local sales representative or use the **Compatibility List** to determine the components to be used.

- The memory can be used with Intel® Xeon® Scalable Skylake and Cascade Lake processors. The maximum memory capacity supported varies depending on the processor model.
  - Skylake processors
    - M processors: 1.5 TB/socket
    - Other processors: 768 GB/socket
  - Cascade Lake processors
    - L processors: 4.5 TB/socket
    - M processors: 2 TB/socket
    - Other processors: 1 TB/socket
- The total memory capacity is the sum of the capacity of all DDR4 DIMMs.

NOTICE

The total memory capacity cannot exceed the maximum memory capacity supported by the CPUs.

- Use the **Compatibility List** to determine the capacity type of a single memory module.
- The maximum number of DIMMs supported by a server varies depending on the CPU type, memory type, rank quantity, and operating voltage.

NOTE

Each memory channel supports a maximum of 8 ranks. The number of DIMMs supported by each channel varies depending on the number of ranks supported by each channel:

Number of DIMMs supported by each channel ≤ Number of ranks supported by each memory channel/Number of ranks supported by each DIMM

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Table 5-6 DDR4 memory specifications

Parameter		DIMM				
Maximum capacity per DDR4 DIMM (GB)		16	16	32	32	64
Rated speed (MT/s)		2666	2933	2666	2933	2933
Rank		Dual rank	Dual rank	Dual rank	Dual rank	Dual rank
Operating voltage (V)		1.2	1.2	1.2	1.2	1.2
Maximum number of DDR4 DIMMs in a server[a]		12	12	12	12	12
Maximum DDR4 memory capacity of the server (GB)[b]		192	192	384	384	768
Maximum operating speed (MT/s)	1DPC[c]	2666	2933[d]	2666	2933[d]	2933[d]

- a: The maximum number of DDR4 memory modules is based on dual-processor configuration. The value is halved for a server with only one processor.
- b: The maximum DDR4 memory capacity varies depending on the processor type. The value listed in this table is based on the assumption that DIMMs are fully configured.
- c: DPC (DIMM per channel) indicates the number of DIMMs per channel.
- d: If the Cascade Lake processor is used, the maximum operating speed of a DIMM can reach 2933 MT/s. If the Skylake processor is used, the maximum operating speed of a DIMM can reach 2666 MT/s only. Different CPUs possess different specifications, For details about the CPU parameters, see the Intel official website.
- The information listed in this table is for reference only. For details, consult the local sales representative.

5.4.1.4 DIMM Installation Rules

- Observe the following when configuring DDR4 memory modules:
  - Install memory modules only when corresponding processors are installed.
  - Do not install LRDIMMs and RDIMMs in the same server.
  - Install filler memory modules in vacant slots.
- Observe the following when configuring DDR4 memory modules in specific operating mode:
  - Memory sparing mode

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- Comply with the general installation guidelines.
- Each memory channel must have a valid online spare configuration.
- The channels can have different online spare configurations.
- Each populated channel must have a spare rank.

– Memory mirroring mode
  - Comply with the general installation guidelines.
  - Each processor supports two integrated memory controllers (IMCs). At least two channels of each IMC are used for installing memory modules (channels 1 and 2, or channels 1, 2, and 3). The installed memory modules must be identical in size and organization.
  - For a multi-processor configuration, each processor must have a valid memory mirroring configuration.

– Memory scrubbing mode
  - Comply with the general installation guidelines.

5.4.1.5 Memory Installation Positions

A 2298 V5 supports a maximum of 12 DDR4 DIMMs. To maximize the performance, balance the total memory capacity between the installed processors and load the channels similarly whenever possible.

NOTICE

At least one DDR4 DIMM must be installed in the memory slots corresponding to CPU 1.

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Figure 5-9 Memory slots

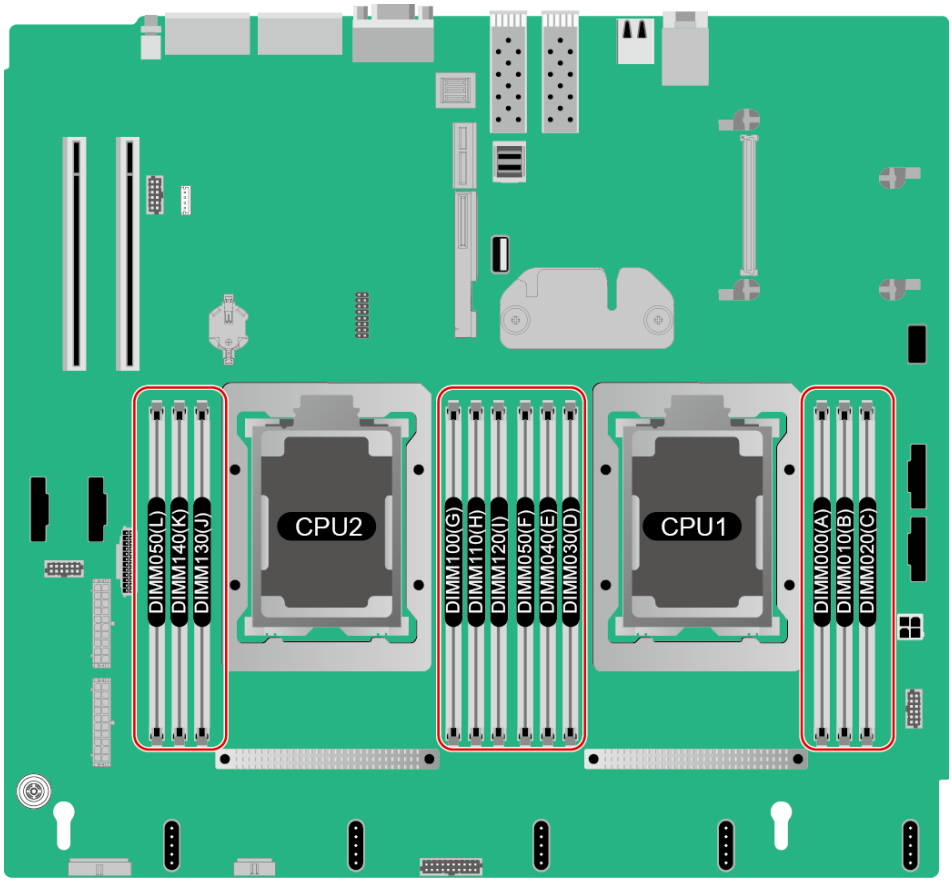

Figure 5-10 DDR4 memory installation guidelines (1 processor)

CPU	Channel	DIMM Slot	Number of DIMMs (✓: recommended ○: not recommended)					
			✓	✓	✓	✓	○	✓
			1	2	3	4	5	6
CPU1	A	DIMM000(A)	●	●	●	●	●	●
	B	DIMM010(B)		●	●	●	●	●
	C	DIMM020(C)			●		●	●
	D	DIMM030(D)				●	●	●
	E	DIMM040(E)				●	●	●
	F	DIMM050(F)						●

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Figure 5-11 DDR4 memory installation guidelines (2 processors)

CPU	Channel	DIMM Slot	Number of DIMMs (✓: recommended O: not recommended)											
			O	✓	O	✓	O	✓	O	✓	O	O	O	✓
			1	2	3	4	5	6	7	8	9	10	11	12
CPU1	A	DIMM000(A)	●	●	●	●	●	●	●	●	●	●	●	●
	B	DIMM010(B)			●	●	●	●	●	●	●	●	●	●
	C	DIMM020(C)					●	●			●	●	●	●
	D	DIMM030(D)							●	●	●	●	●	●
	E	DIMM040(E)							●	●	●	●	●	●
	F	DIMM050(F)											●	●
CPU2	G	DIMM100(G)		●	●	●	●	●	●	●	●	●	●	●
	H	DIMM110(H)				●	●	●	●	●	●	●	●	●
	I	DIMM120(I)						●	●		●	●	●	●
	J	DIMM130(J)								●	●	●	●	●
	K	DIMM140(K)								●		●	●	●
	L	DIMM150(L)												●

5.4.1.6 Memory Protection Technologies

The following memory protection technologies are supported:

- ECC
- Full mirroring
- Address range mirroring
- SDDC
- SDDC+1
- Rank sparing mode
- Static virtual lockstep
- Faulty DIMM isolation
- Memory thermal throttling
- Memory address parity protection
- Memory demand/patrol scrubbing
- Device tagging
- Data scrambling
- Adaptive double device data correction (ADDDC)
- ADDDC+1

5.5 Storage

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5.5.1 Drive Configuration

Table 5-7 Drive configuration

Configuration	Maximum Number of Front Drawer Drives	Maximum Number of Rear Drives	Maximum Number of Built-in Drives	Drive Management Mode
Configuration 1	● Front drawer drive (24 x 3.5): 24 – Slots 0 to 23 support only SAS/SATA drives.	● Rear drive (4 x 2.5): 4 – Slots R0 to R3 support SAS/SATA/NVMe drives	● Built-in drive: 2 – Two built-in M.2 SSDs[a]	● Front drawer drive: SAS HBA card[b] ● Rear drive: PCIe RAID controller card[c]/PCH pass-through[d]/CPU pass-through[e] The PCIe RAID controller card must be installed in slot 2 ● Built-in drive: PCH pass-through

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Configuration	Maximum Number of Front Drawer Drives	Maximum Number of Rear Drives	Maximum Number of Built-in Drives	Drive Management Mode
Configuration 2	• Front drawer drive (24 x 3.5): 24 – Slots 0 to 23 support only SAS/SATA drives.	• Rear drive (4 x 2.5): 4 – Slots R0 to R3 support SAS/SATA/NVMe drives	• Built-in drive: 2 – Two built-in M.2 SSDs[a]	• Front drawer drive: 2 x PCIe RAID controller cards PCIe RAID controller card: It must be configured in slots 1 and 2[f] • Rear drive: PCIe RAID controller card[c]/CPU pass-through[e] The PCIe RAID controller card must be installed in slot 2[f] • Built-in drive: PCH pass-through

- a: The M.2 SSDs come in two sizes 2242 and 2280, and supports SATA and PCIe interfaces.
- b: Front hard drives are configured with 24-port SAS HBAs.
- c: Supports PCIe RAID controller cards when the rear drives are configured with SATA or SAS drives.
- d: Supports PCH pass-through when the rear drive is configured with SATA drives.
- e: Supports CPU pass-through when the rear drive is configured with NVMe drives.
- f: The PCIe RAID controller card in slot 2 manages both front drawer drives and rear drives.
- Contact your local sales representative or use the **Compatibility List** to determine the components to be used.

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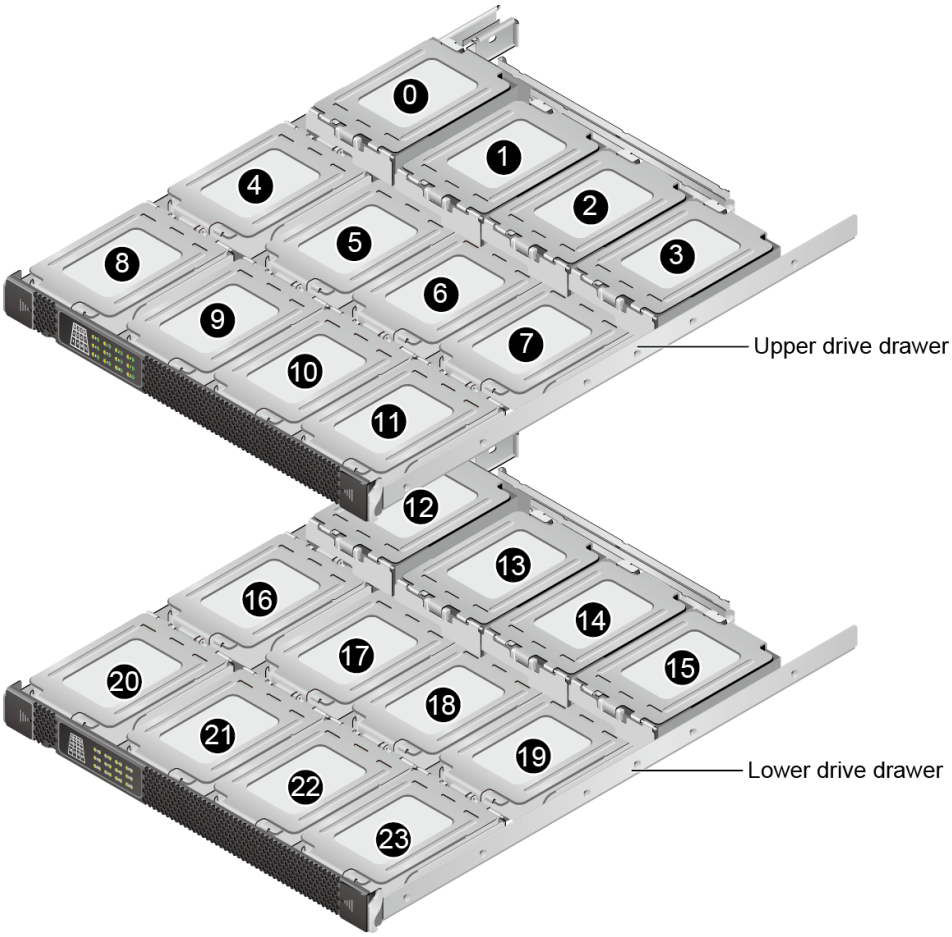
5.5.2 Drive Numbering

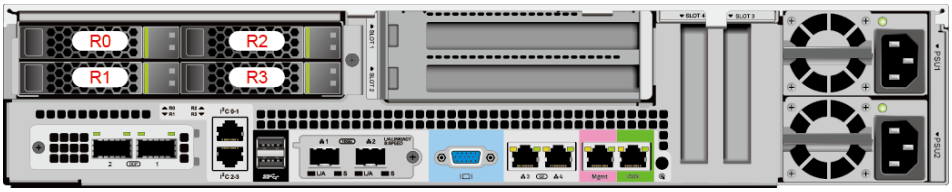
- Front drives

Figure 5-12 Drive numbering



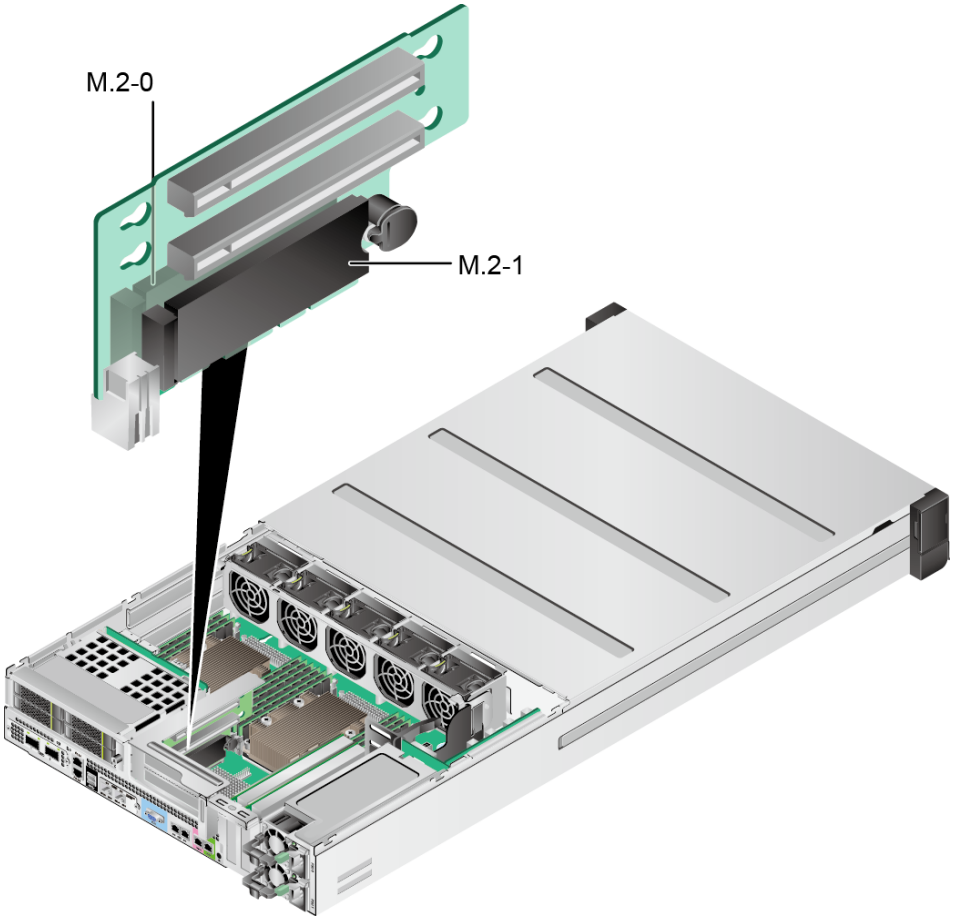
- Rear drives

Figure 5-13 Drive numbering



- Built-in drives (M.2 SSD-0/1)

Figure 5-14 Drive numbering



5.5.3 Drive Indicators

Front Drive Drawer Indicators (3.5-inch SAS/SATA drives)

Figure 5-15 Indicators of the front drive drawer

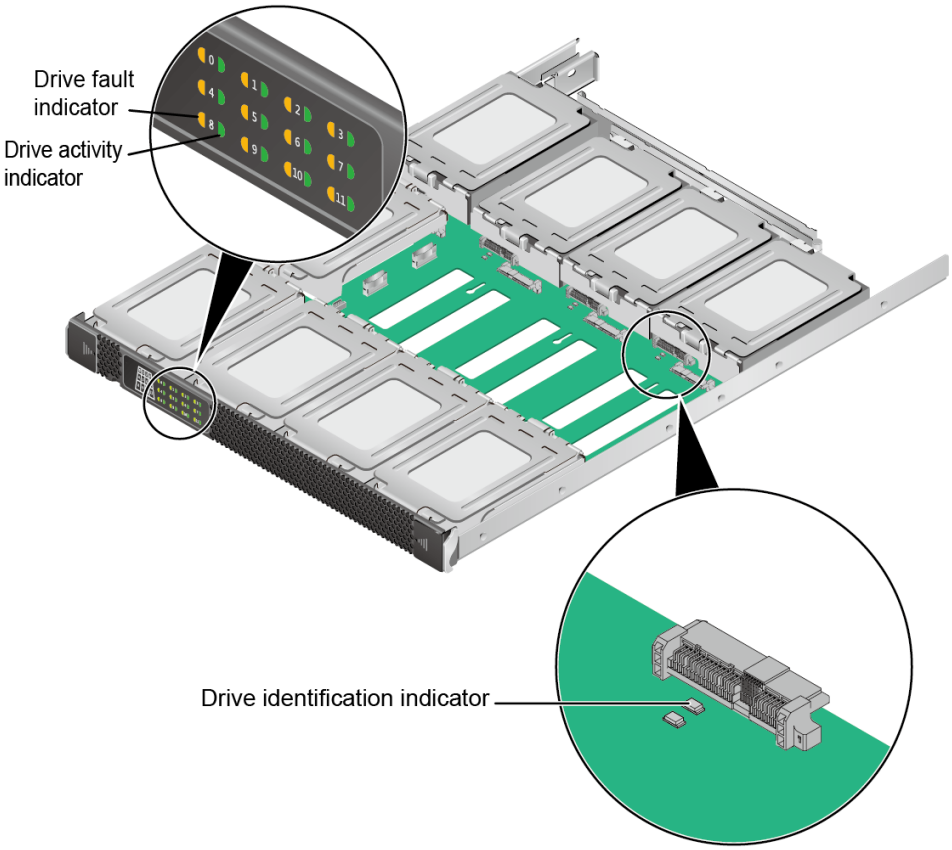


Table 5-8 Description of identification indicators of the front drive drawer

Drive Identification Indicator (Blue)	Description
Steady on	The drive is being located.
Off	The drive is not in position.

Table 5-9 Description of status indicators of the front drive drawer

Activity Indicator (Green)	Fault Indicator (Yellow)	Description
Blinking at 0.5 Hz	Off	The RAID group is being rebuilt or the member drive is being replaced.
Blinking at 1 Hz	Off	The drive is being identified or to be deleted.

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Activity Indicator (Green)	Fault Indicator (Yellow)	Description
Blinking	Off	The drive is being accessed. **NOTE** The blinking speed indicates the number of I/Os.
Steady on	Off	The drive is online.
Off	Blinking at 8 Hz	The drive is faulty.
Blinking (on for 0.5s and off for 1s)	Blinking (on for 0.5s and off for 1s)	The drive is in prefail state.
Blinking (on for 3s and off for 3s)	Blinking (on for 3s and off for 3s)	The RAID group rebuilding is suspended.
Off	Off	The drive is not in position.

SAS/SATA Drive Indicators

Figure 5-16 SAS/SATA drive indicators

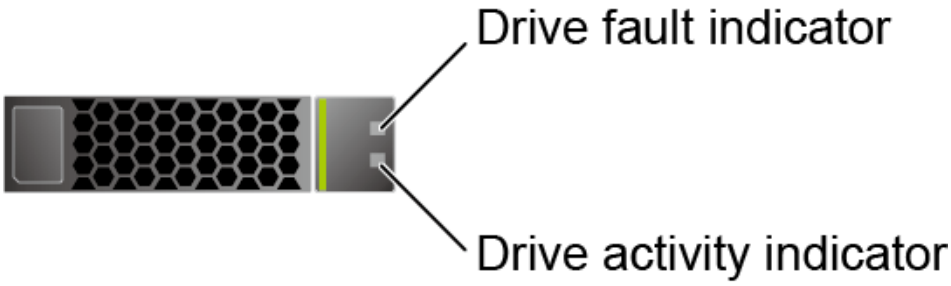

Table 5-10 Description of SAS/SATA drive indicators

Activity Indicator (Green)	Fault Indicator (Yellow)	Description
Off	Off	The drive is not in position.
Steady on	Off	The drive is detected.
Blinking at 4 Hz	Off	Data is being read or written normally, or data on the primary drive is being rebuilt.
Steady on	Blinking at 1 Hz	The drive is being located.
Blinking at 1 Hz	Blinking at 1 Hz	Data on the secondary drive is being rebuilt.
Off	Steady on	A member drive in the RAID array is removed.

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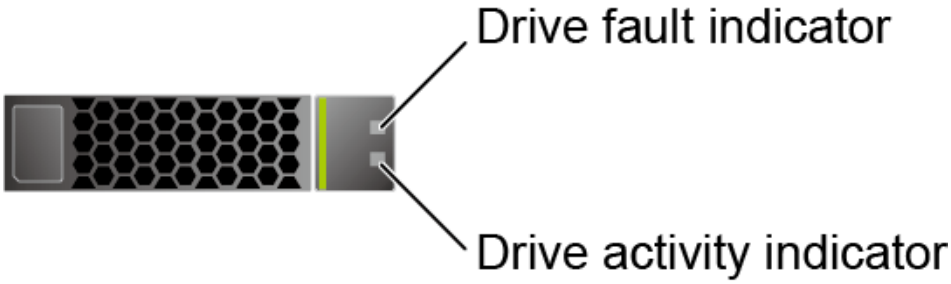
Activity Indicator (Green)	Fault Indicator (Yellow)	Description
Steady on	Steady on	The drive is faulty.

NVMe Drive Indicators

Figure 5-17 NVMe drive indicators



- If the VMD function is enabled and the latest VMD driver is installed, the NVMe drives support surprise hot swap.

Table 5-11 NVMe drive indicators (VMD enabled)

Activity Indicator (Green)	Fault Indicator (Yellow)	Description
Off	Off	The NVMe drive cannot be detected.
Steady on	Off	The NVMe drive is working properly.
Blinking at 2 Hz	Off	Data is being read from or written to the NVMe SSD.
Steady on	Blinking at 2 Hz	The NVMe drive is being located.
Steady on/Off	Steady on	The NVMe drive is faulty.

- If the VMD function is disabled, NVMe drives support only orderly hot swap.

Table 5-12 NVMe drive indicators (VMD disabled)

Activity Indicator (Green)	Fault Indicator (Yellow)	Description
Off	Off	The NVMe drive cannot be detected.
Steady on	Off	The NVMe drive is working properly.

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Activity Indicator (Green)	Fault Indicator (Yellow)	Description
Blinking at 2 Hz	Off	Data is being read from or written to the NVMe drive.
Off	Blinking at 2 Hz	The NVMe drive is being located or hot-swapped.
Off	Blinking at 0.5 Hz	The hot removal process is complete, and the NVMe drive is removable.
Steady on/Off	Steady on	The NVMe drive is faulty.

M.2 FRU Indicators

Figure 5-18 M.2 FRU indicators

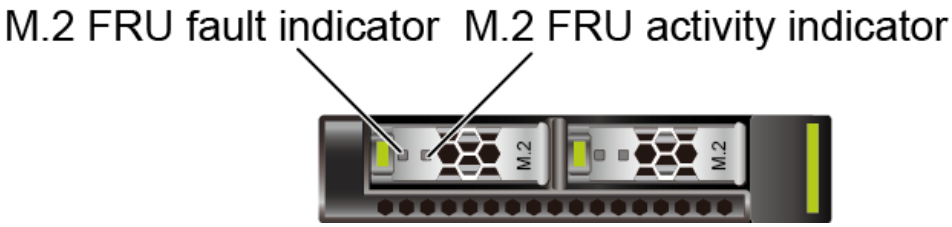

Table 5-13 M.2 FRU indicator description

Indicator	Description
M.2 FRU fault indicator	• Off: The M.2 FRU is running properly. • Blinking yellow: The M.2 FRU is being located, or RAID is being rebuilt. • Steady yellow: The M.2 FRU is faulty or not detected.
M.2 FRU activity indicator	• Off: The M.2 FRU is not in position or is faulty. • Blinking green: Data is being read, written, or synchronized. • Steady green: The M.2 FRU is inactive.

5.5.4 RAID Controller Card

The RAID controller card supports RAID configuration, RAID level migration, and drive roaming.

- If SAS/SATA drives are used as rear drives, a RAID controller card can be configured to manage the rear drives.
  - Contact your local sales representative or use the **Compatibility List** to determine the components to be used.

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– For details about the RAID controller card, see **V5 Server RAID Controller Card User Guide**.

5.6 Network

5.6.1 LOMs

LOMs provide network expansion capabilities.

Table 5-14 LOMs supported by the 2298 V5

NIC Type	Chip Model	Port Type	Number of Ports	Rate Negotiation Mode	Supported Rates	Rates Not Supported
LOMs	X722	10GE optical port	2	Auto-negotiation 10,000 Mbit/s (full duplex)	10000M	10/100/1000M
		GE electrical port	2	Auto-negotiation 1000 Mbit/s (full duplex)	1000M	10/100M

- Use **Compatibility List** to obtain information about the cables and optical modules supported by the LOM ports.
- The LOM ports support NC-SI, WOL, and PXE.
- The LOM ports do not support forced rates.
- The electrical LOM ports cannot be connected to power over Ethernet (PoE) devices (such as a switch with PoE enabled). Connecting a LOM port to a PoE device may cause link communication failure or even damage the NIC.
- The electrical LOM ports (GE electrical ports) do not support SR-IOV.
- Forcibly powering off a server will cause intermittent NC-SI disconnection and disable the WOL function of the LOM ports. To restore the NC-SI connection, refresh the iBMC WebUI.

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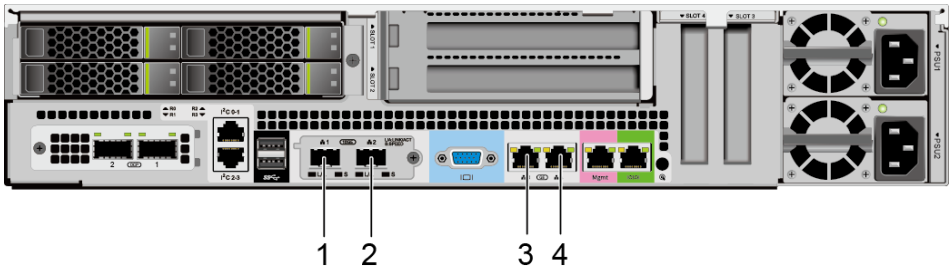
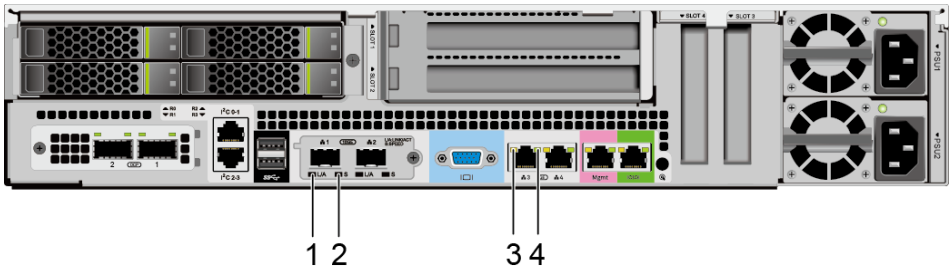
Figure 5-19 LOM port



1	10GE optical port (LOM port 1)	2	10GE optical port (LOM port 2)
3	GE electrical port (LOM port 3)	4	GE electrical port (LOM port 4)

Indicator Positions

Figure 5-20 LOM indicators



1	Connection status indicator/Data transmission status indicator for a 10GE optical port	2	Data transmission rate indicator for a 10GE optical port
3	Data transmission status indicator of a GE electrical port	4	Connection status indicator of a GE electrical port

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Indicator Description

Table 5-15 LOM indicators

Indicator	Description
Connection status indicator/Data transmission status indicator for a 10GE optical port	• Off: The network port is not connected. • Blinking green: Data is being transmitted. • Steady green: The network port is properly connected.
Data transmission rate indicator for a 10GE optical port	• Off: The network port is not connected. • Steady green: The data transmission rate is 10 Gbit/s.
Data transmission status indicator of a GE electrical port	• Off: Inactive. • Steady yellow: Active, but no data is being transmitted. • Blinking yellow: Data is being transmitted.
Connection status indicator of a GE electrical port	• Off: The network port is not connected. • Steady green: The network port is properly connected.

5.6.2 OCP 2.0 Mezzanine Cards

OCP 2.0 mezzanine cards provide network expansion capabilities.

- Supports on-demand configuration.
- Contact your local sales representative or use the **Compatibility List** to determine the components to be used.

Table 5-16 OCP 2.0 mezzanine card supported by the 2298 V5

NIC Type	Chip Model	Port Type	Number of Ports	NC-SI	WOL	PXE
OCP 2.0 mezzanine card	CX5	25GE optical port	2	√	√	√

Indicator Positions

- OCP 2.0 mezzanine card indicators (2 x 25GE optical ports)

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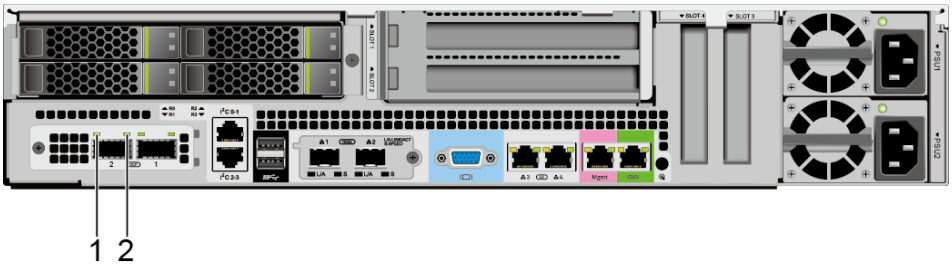
Figure 5-21 OCP 2.0 mezzanine card indicators (2 x 25GE optical ports)



1	Connection status indicator/Data transmission status indicator for a 25GE optical port	2	Data transmission rate indicator for a 25GE optical port

Indicator Description

Table 5-17 OCP 2.0 mezzanine card indicators

Indicator	Description
Connection status indicator/Data transmission status indicator for a 25GE optical port	• Off: The network port is not connected. • Blinking green: Data is being transmitted. • Steady green: The network port is properly connected.
Data transmission rate indicator for a 25GE optical port	• Off: The network port is not connected. • Steady green: The data transmission rate is 25 Gbit/s. • Steady yellow: The data transmission rate is 10 Gbit/s.

5.7 I/O Expansion

5.7.1 PCIe Cards

PCIe cards provide ease of expandability and connection.

- Four slots for standard PCIe cards are supported.
- The electrical ports provided by PCIe NICs cannot be connected to power over Ethernet (PoE) devices (such as a switch with PoE enabled). Connecting such an electrical port to a PoE device may cause link communication failure or even damage the NIC.
- Contact your local sales representative or use the **Compatibility List** to determine the components to be used.

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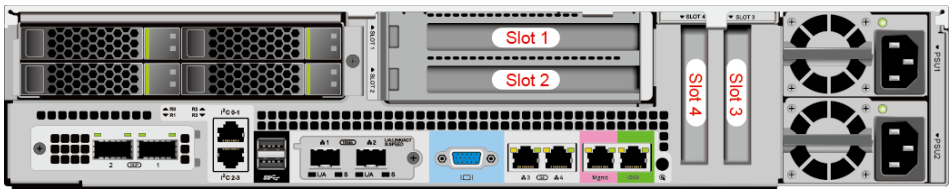
5.7.2 PCIe Slots

PCIe Slots

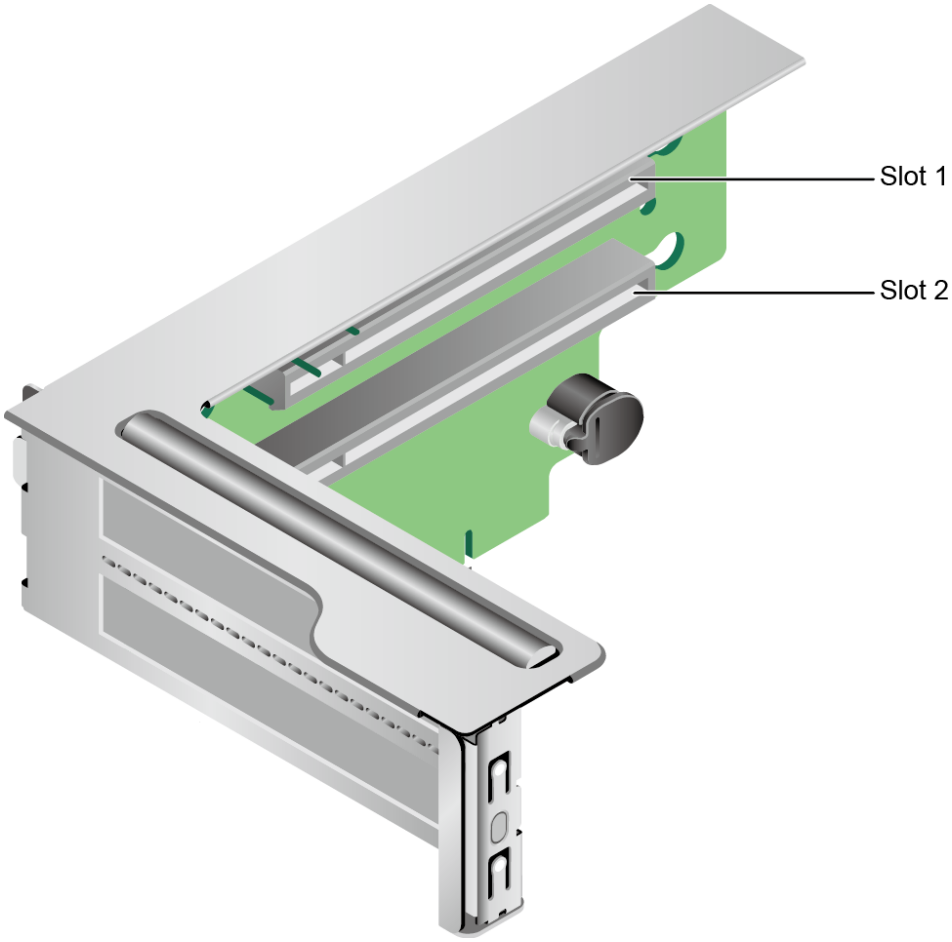
Figure 5-22 PCIe slots



- Slots 1 and 2 are provided by the PCIe riser module. By default, slot 1 is configured with a 24-port SAS HBA card.
- Slots 3 and 4 are provided by the mainboard.

PCIe Riser Module

Figure 5-23 PCIe riser module



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5.7.3 PCIe Slot Description

NOTE

The PCIe slots mapping to a vacant CPU socket are unavailable.

Table 5-18 PCIe slot description

PCIe Slot	CPU	PCIe Standards	Connector Width	Bus Width	Port No.	Root Port (B/D/F)	Device (B/D/F)	Slot Size
LOM	CPU1	PCIe 3.0	x8	x8	Port1C	85/02/0	89/00/0	-
OCP 2.0 mezzanine card	CPU 1	PCIe 3.0	x8	x8	Port1A	17/00/0	18/00/0	-
Slot 1	CPU 1	PCIe 3.0	x16	x8	Port3A	5D/00/0	5E/00/0	FHHL
Slot 2	CPU 1	PCIe 3.0	x16	x8	Port3C	5D/02/0	5F/00/0	FHHL
Slot 3	CPU 2	PCIe 3.0	x16	x16	Port1A	85/00/0	85/00/0	HHHL
Slot 4	CPU 2	PCIe 3.0	x16	x16	Port2A	AE/00/0	AE/00/0	HHHL

- The B/D/F (Bus/Device/Function Number) values are the default values when the server is fully configured with PCIe devices. The values may vary if the server is not fully configured with PCIe devices or if a PCIe card with a PCI bridge is configured.
- Root Port (B/D/F) indicates the B/D/F of an internal PCIe root port of the processor.
- Device (B/D/F) indicates the B/D/F (displayed on the OS) of an onboard or extended PCIe device.
- The PCIe x16 slots are backward compatible with PCIe x8, PCIe x4, and PCIe x1 cards. The PCIe cards are not forward compatible. That is, the PCIe slot width cannot be smaller than the PCIe card link width.
- The full-height half-length (FHHL) PCIe slots are backward compatible with half-height half-length (HHHL) PCIe cards.
- All slots support PCIe cards of up to 75 W. The power of a PCIe card varies depending on its model.
- The SP520, SP521, and SP522 do not support driveless server configuration. PXE boot is recommended for driveless servers.

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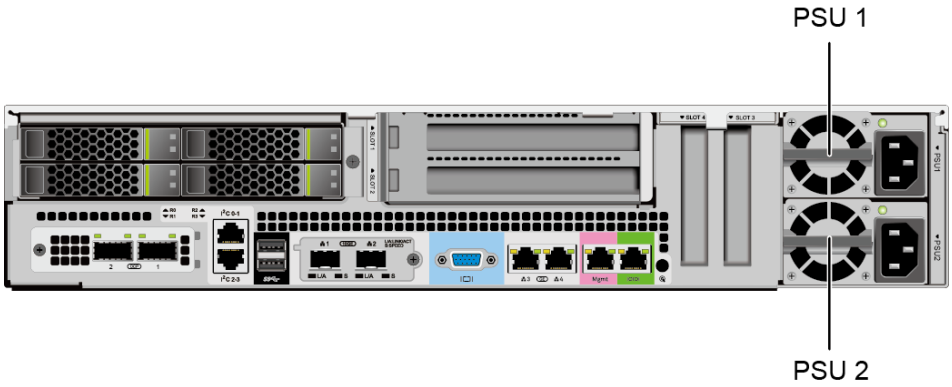
5.8 PSUs

- The server supports one or two PSUs.
- The server supports AC or DC PSUs.
- The PSUs are hot-swappable.
- The server supports two PSUs in 1+1 redundancy.
- The same model of PSUs must be used in a server.
- The PSUs are protected against short circuit. Double-pole fuse is provided for the PSUs with dual input live wires.
- If the DC power supply is used, purchase the DC power supply that meets the requirements of the safety standards or the DC power supply that has passed the CCC certification.
- Contact your local sales representative or use the **Compatibility List** to determine the components to be used.

NOTE

When one or two 1500 W AC Platinum PSUs are configured, When the input voltage ranges from 100 V AC to 127 V AC, the output power decreases to 1000 W.

Figure 5-24 PSU positions



5.9 Fans

- The server supports five fan modules.
- The fan modules are hot-swappable.
- The server tolerates failure of a single fan.
- The fan speed can be adjusted.
- The same model of fan modules must be used in a server.

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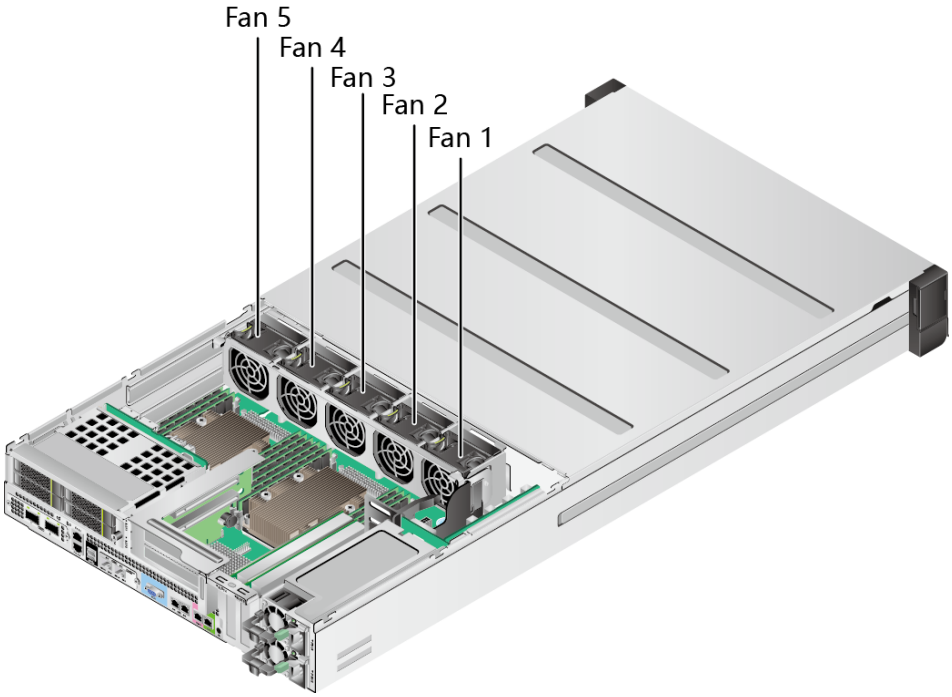
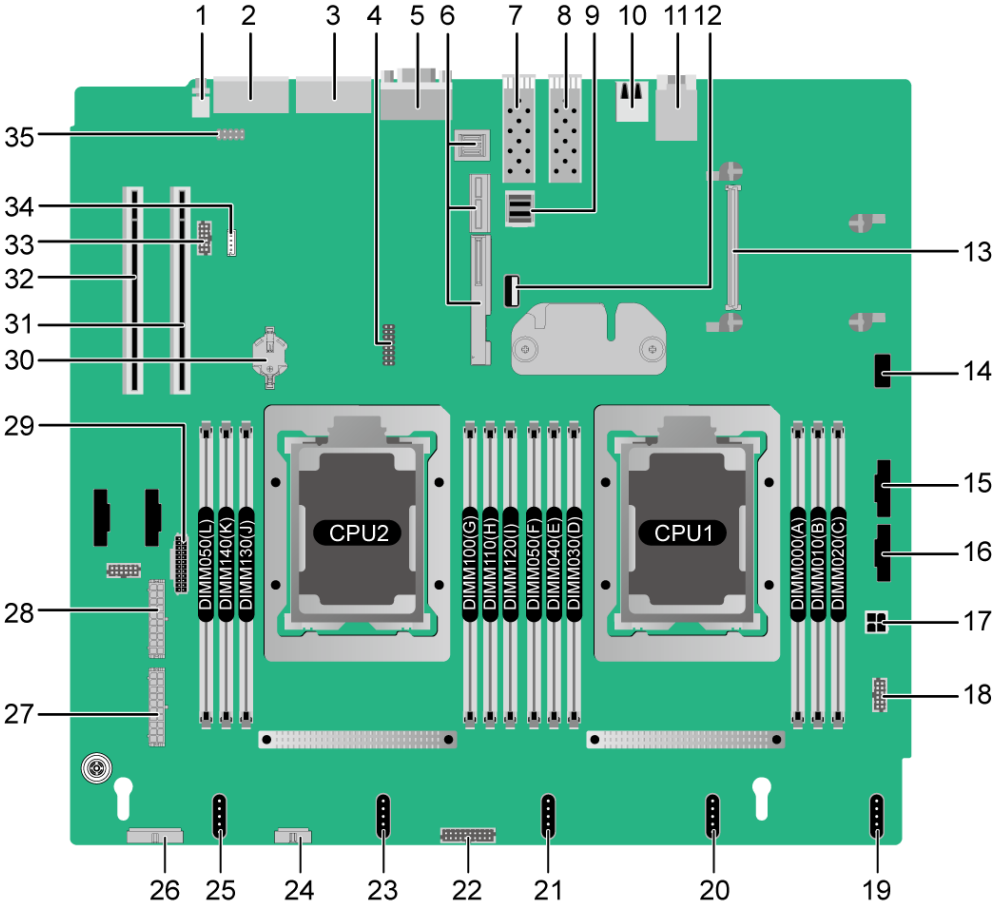
Figure 5-25 Fan module positions



5.10 Boards

5.10.1 Mainboard

Figure 5-26 2298 V5 mainboard



1	UID button/indicator (S1)	2	Management network port + serial port (J13)
3	LOM GE port (J11)	4	TPM/TCM port (TPM CONN/J55)
5	VGA connector (VGA CONN/J112)	6	PCIe riser slot (PCIE RISER/J1/J8/J9)
7	10GE optical port (J132)	8	10GE optical port (J131)
9	mini-SAS HD connector (MINIHD PORTA/J86)	10	USB 3.0 port (USB3.0 CONN/J169)
11	I^2C management network port (I2C/J10)[a]	12	USB 3.0 port (INNER USB3.0/J173)
13	OCP 2.0 mezzanine card slot (OCP CARD/J5)	14	Right mounting ear connector (REAR BOARD/ J186)

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15	CPU 1 slimline connector (CPU0 PORTA/J181)	16	CPU 1 slimline connector (CPU0 PORTB/J170)
17	Rear-drive backplane power connector (PWR OUT/J172)	18	Rear-drive backplane management connector (REAR HDD BP/J164)
19	Fan 5 port (FAN4/J143)	20	Fan 4 port (FAN3/J102)
21	Fan 3 port (FAN2/J103)	22	Upper drive drawer management cable connector (HDD BP CONN0/J7)
23	Fan 2 port (FAN1/J104)	24	Left mounting ear connector (LEAR BOARD/ J167)
25	Fan 1 port (FAN0/J105)	26	Lower drive drawer management cable connector (HDD BP CONN1/J162)
27	Mainboard power connector (PWR IN1/J185)	28	Mainboard power connector (PWR IN0/J184)
29	PSU management connector (J182)	30	RTC battery (CMOS BATTERY/U4042)
31	Onboard PCIe slot (J179)	32	Onboard PCIe slot (J180)
33	PCIe standard card NC-SI port (NCSI CONN/J99)	34	VROC key port (SOFT RAID KEY/J130)[a]
35	Jumper (J176)[b]	-	-

- a: The port is reserved.
- b: The COM_SW(ON) is used for changing the connection direction of the physical serial port.

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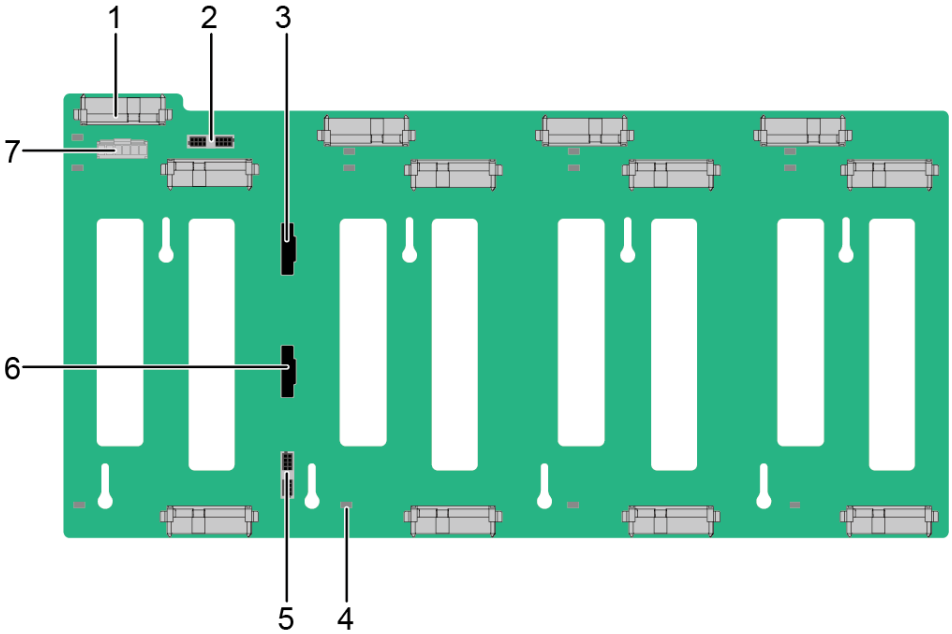
5.10.2 Drive Backplane

Front Drawer Drive Backplane

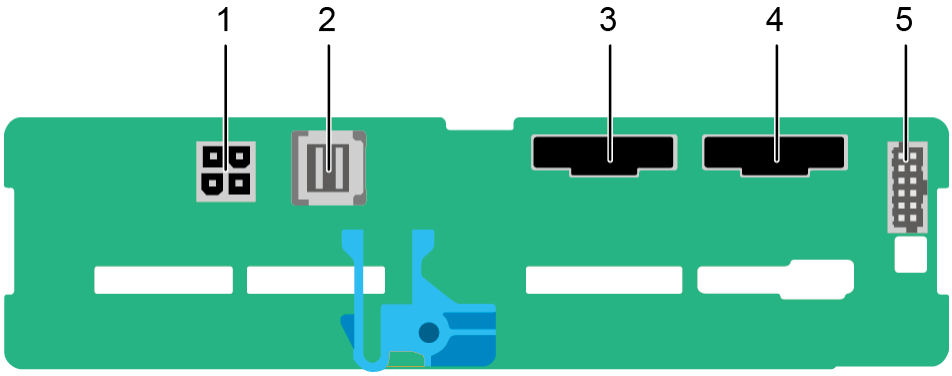
Figure 5-27 Front drawer drive pass-through backplane (BOM 03025YVL)



1	Drive connector (J20)	2	Backplane management signal cable connector (J1)
3	Slimline connector (PORT A)	4	Drive identification indicator
5	Indicator signal cable connector (J1701)	6	Slimline connector (PORT B)
7	Power connector (J2)	-	-

Rear-Drive Backplane

Figure 5-28 Rear-drive pass-through backplane (BOM: 03024BPV and 03029TDR)



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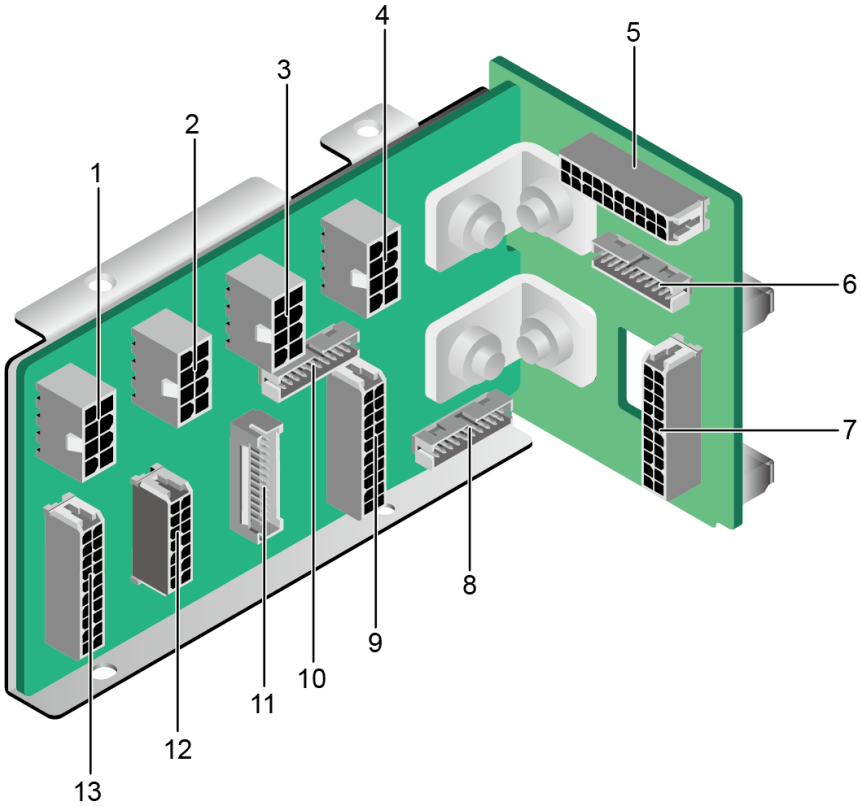
1	Power connector (REAR BP POWR3/J22)	2	mini-SAS HD connector (Port A/J2)
3	Slimline A connector (SLIMLINE A/J8)	4	Slimline B connector (SLIMLINE B/J9)
5	Backplane signal cable connector (HDD BP/J23)	-	-

5.10.3 PSU Backplane

Figure 5-29 2298 V5 PSU backplane



1	Backplane power connector (J11)[a]	2	Backplane power connector (J10)[a]
3	Backplane power connector (J9)	4	Backplane power connector (J8)
5	Mainboard power connector (J4)	6	PSU signal connector (J5)
7	Mainboard power connector (J3)	8	PSU signal connector (J16)[a]

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9	Power connector (J6)[a]	10	PSU signal connector (J17)
11	Mainboard power signal connector (J15)	12	Backplane power connector (J12)[a]
13	Backplane power connector (J14)[a]	-	-
a: The port is reserved.			

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6 Product Specifications

6.1 Technical Specifications
6.2 Environmental Specifications
6.3 Physical Specifications

6.1 Technical Specifications

Table 6-1 Technical Specifications

Component	Specifications
Form factor	2U rack server
Chipset	Intel® C622
Processor	Supports one or two processors. ● Intel® Xeon® Scalable (Skylake and Cascade Lake) processors ● Built-in memory controller and six memory channels ● Built-in PCIe controller, supporting PCIe 3.0 and 48 lanes per processor ● Two UPI buses between processors, providing up to 10.4GT/s transmission per channel ● Up to 28 cores per processor ● Max. 3.8 GHz ● Min. 1.375 MB L3 cache per core ● Max. 205 W TDP **NOTE** The preceding information is for reference only. Use the **Compatibility List** to obtain specific information.

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Component	Specifications
DIMM	Supports 12 memory modules of the following types: ● Up to 12 DDR4 memory modules ● Compatible with 3200 MT/s DDR4 memory modules. The actual memory speed is subject to Intel CPU specifications. ● RDIMM and LRDIMM support ● The DDR4 memory modules of different types (RDIMM and LRDIMM) and specifications (capacity, bit width, rank, and height) cannot be used together. **NOTE** The preceding information is for reference only. Use the **Compatibility List** to obtain specific information.

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Component	Specifications
Storage	Supports a variety of drive configurations. For details, see **5.5.1 Drive Configuration**. ● Supports two M.2 SSDs. **NOTE** ● The M.2 SSD module is used only as the boot device when the OS is installed. Small-capacity (32 GB or 64 GB) M.2 SSDs do not support logging due to poor endurance. If a small-capacity M.2 SSD is used as the boot device, a dedicated log drive or log server is required for logging. For example, you can dump VMware logs in either of the following ways: ● Redirect **/scratch**. For details, see **https://kb.vmware.com/s/article/1033696**. ● Configure syslog. For details, see **https://kb.vmware.com/s/article/2003322**. ● The M.2 SSD cannot be used to store data due to poor endurance. In write-intensive applications, the M.2 SSD will wear out in a short time. Use enterprise-level high endurance (HE) SSDs or HDDs for data storage. ● The M.2 SSD is not recommended for write-intensive service software due to poor endurance. ● Do not use the M.2 SSD as the cache. ● Supports hot swap of SAS/SATA/NVMe U.2 drives. **NOTE** The NVMe drives support: ● Surprise hot swap if the VMD function is enabled and the latest Intel VMD driver is installed. ● Orderly hot swap if the VMD function is disabled. ● Supports a variety of RAID controller cards. Use the **Compatibility List** to obtain information about the specific RAID controller cards supported. – The RAID controller card supports RAID configuration, RAID level migration, and drive roaming. – The PCIe RAID controller card occupies one standard PCIe slot. For details about the RAID controller card, see ***V5 Server RAID Controller Card User Guide***. ● Supports the 24-port SAS HBA card to improve storage performance and data security. **NOTE** If the BIOS is in legacy mode, the 4K drive cannot be used as the boot drive.

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Component	Specifications
Network	Supports expansion capability of multiple types of networks. ● LOM – Supports two 10GE optical ports and two GE electrical ports via the NIC chip integrated on the mainboard. – The LOM ports support NC-SI, WOL, and PXE. ● OCP 2.0 mezzanine card – Supports on-demand configuration. – Supports a variety of OCP 2.0 mezanine cards. Use the **Compatibility List** to obtain information about the specific OCP 2.0 cards supported. **NOTE** The electrical ports provided by LOMs and PCIe NICs cannot be connected to PoE devices (such as a switch with PoE enabled). Connecting such an electrical port to a PoE device may cause link communication failure or even damage the NIC.
I/O expansion	5 PCIe 3.0 slots: ● One slot dedicated for an OCP 2.0 mezzanine card and four for standard PCIe cards. For details, see **5.7.2 PCIe Slots** and **5.7.3 PCIe Slot Description**. **NOTE** The preceding information is for reference only. Use the **Compatibility List** to obtain specific information.
Port	Supports a variety of ports. ● Ports on the front panel: – Two USB 3.0 ports – One DB15 VGA port ● Ports on the rear panel: – Two USB 3.0 ports – One DB15 VGA port – One RJ45 serial port – One RJ45 system management port – Two GE electrical ports – Two 10GE optical ports ● Built-in port: – One USB 3.0 port **NOTE** You are not advised to install the operating system on the USB storage media.

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Component	Specifications
Video card	An SM750 video chip with 32 MB display memory is integrated on the mainboard. The maximum display resolution is 1920 x 1200 at 60 Hz with 16 M colors. **NOTE** ● SM750 is not supported by servers running the Windows Server 2019 or Windows Server 2019 Hyper-V operating systems that are in secure boot mode. ● The integrated video card can provide the maximum display resolution (1920 x 1200) only after the video card driver matching the operating system version is installed. Otherwise, only the default resolution supported by the operating system is provided. ● If both the front and rear VGA ports of a device are connected to a monitor, the front VGA port is used by default.
System management	● Supports UEFI. ● Supports iBMC. ● Supports NC-SI. ● Supports integration with third-party management systems.
Security feature	● Power-on password ● Administrator password ● TCM (only in China)/TPM ● Secure boot

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6.2 Environmental Specifications

Table 6-2 Environmental specifications

Category	Specifications
Temperature	● Operating temperature: 5°C to 35°C (41°F to 95°F) (ASHRAE Class A1/A2 compliant) ● Storage temperature (within three months): –30°C to +60°C (–22°F to +140°F) ● Storage temperature (within six months): –15°C to +45°C (5°F to 113°F) ● Storage temperature (within one year): –10°C to +35°C (14°F to 95°F) ● Maximum rate of temperature change: 20°C (36°F) per hour, 5°C (9°F) per 15 minutes **NOTE** The highest operating temperature varies depending on the server configuration. For details, see **A.3 Operating Temperature Limitations**.
Relative humidity (RH, non-condensing)	● Operating humidity: 8% to 90% ● Storage humidity (within three months): 8% to 85% ● Storage humidity (within six months): 8% to 80% ● Storage humidity (within one year): 20% to 75% ● Maximum change rate: 20%/h
Air volume	≥ 110 cubic feet per minute (CFM)
Operating altitude	≤3050m ● When the server configuration complies with ASHRAE Classes A1 and A2 and the altitude is above 900 m (2952.76 ft), the highest operating temperature decreases by 1°C (1.8°F) for every increase of 300 m (984.25 ft). ● HDDs cannot be used at an altitude of over 3050 m (10006.44 ft).
Corrosive gaseous contaminant	Maximum corrosion product thickness growth rate: ● Copper corrosion rate test: 300 Å/month (meeting level G1 requirements of the ANSI/ISA-71.04-2013 standard on gaseous corrosion) ● Silver corrosion rate test: 200 Å/month

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Category	Specifications
Particle contaminant	● The equipment room environment meets the requirements of ISO 14664-1 Class 8. ● There is no explosive, conductive, magnetic, or corrosive dust in the equipment room. **NOTE** It is recommended that the particulate pollution in the equipment room be monitored by a professional agency.
Acoustic noise	The declared A-weighted sound power levels (LWAd) and declared average bystander position A-weighted sound pressure levels (LpAm) listed are measured at 23°C (73.4°F) in accordance with ISO 7779 (ECMA 74) and reported in accordance with ISO 9296 (ECMA 109). ● Idle: – LWAd: 6.7 Bels – LpAm: 52.9 dBA ● Operating: – LWAd: 6.9 Bels – LpAm: 55.6 dBA **NOTE** The noise generated during operation varies depending on the server configuration, load, and ambient temperature.

NOTE

SSDs and HDDs (including NL-SAS, SAS, and SATA) cannot be preserved for a long time in the power-off state. Data may be lost or faults may occur if the preservation duration exceeds the specified maximum duration. When drives are preserved under the storage temperature and humidity specified in the preceding table, the following preservation time is recommended:

- Maximum preservation duration of SSDs:
  - 12 months in power-off state without data stored
  - 3 months in power-off state with data stored
- Maximum preservation duration of HDDs:
  - 6 months in unpacked/packed and powered-off state
- The maximum preservation duration is determined according to the preservation specifications provided by drive vendors. For details, see the manuals provided by drive vendors.

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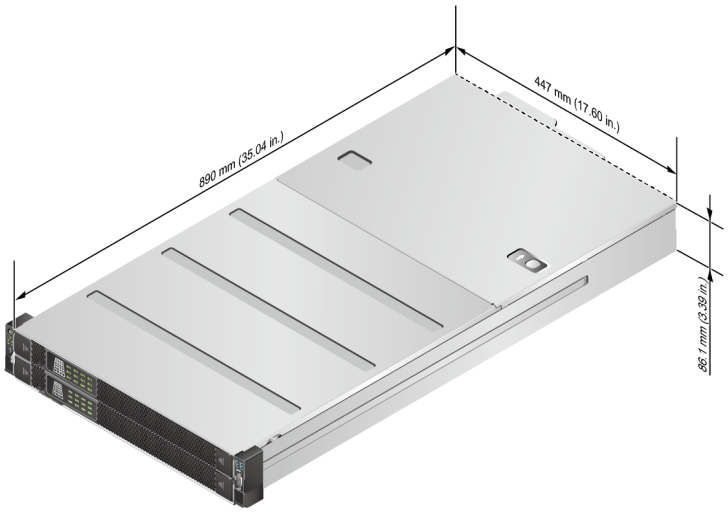
6.3 Physical Specifications

Table 6-3 Physical specifications

Item	Description
Dimensions (H x W x D)	86.1 mmx447 mmx890 mm (3.39 in. x 17.60 in. x 35.04 in.) **Figure 6-1** Physical dimensions  **NOTE** See **Figure 6-1** for methods in measuring physical dimensions of the chassis.
Installation dimension requirements	● Requirements for cabinet installation: Cabinet compliant with the International Electrotechnical Commission (IEC) 297 standard – Cabinet width: 482.6 mm (19 in.) – Cabinet depth ≥ 1100 mm (43.31 in.) ● Requirements for guide rail installation: – Adjustable L-shaped guide rail: apply to cabinets with a distance of 543.5 mm to 848.5 mm (21.40 in. to 33.41 in.) between the front and rear mounting bars.
Fully equipped weight	● Net weight: – Maximum weight for server with 24 x 3.5" drives: 50 kg (110.23 lb) Fully-equipped drives: 24 x 3.5" front drives + 4 x 2.5" rear drives + 2 x M.2 SSDs ● Packaging materials: 5 kg (11.02 lb)

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Item	Description
Energy consumption	The power consumption parameters vary with server configurations, including the configurations complying with energy-related products (ErP) requirements. Use the **Power Calculator** to obtain specific information.

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7 Software and Hardware Compatibility

Use the **Compatibility List** to obtain information about the operating systems and hardware supported.

NOTICE

- If incompatible components are used, the device may be abnormal. This fault is beyond the scope of technical support and warranty.
- The performance of servers is closely related to application software, basic middleware software, and hardware. The slight differences of the application software, middleware basic software, and hardware may cause performance inconsistency between the application layer and test software layer.
  - If the customer has requirements on the performance of specific application software, contact sales personnel to apply for POC tests in the pre-sales phase to determine detailed software and hardware configurations.
  - If the customer has requirements on hardware performance consistency, specify the specific configuration requirements (for example, specific drive models, RAID controller cards, or firmware versions) in the pre-sales phase.

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8 Safety Instructions

8.1 Security

8.2 Maintenance and Warranty

8.1 Security

General Statement

- Comply with local laws and regulations when installing devices. These Safety Instructions are only a supplement.
- The "DANGER", "WARNING", and "CAUTION" information in this document does not represent all the safety instructions, but supplements to the safety instructions.
- Observe all safety instructions provided on the device labels when installing hardware. Follow them in conjunction with these Safety Instructions.
- Only qualified personnel are allowed to perform special tasks, such as performing high-voltage operations and driving a forklift.

WARNING

If this device works in a residential environment, the wireless interference may be generated.

Human Safety

- This equipment is not suitable for use in places where children may be present.
- Only certified or authorized personnel are allowed to install the device.
- Discontinue any dangerous operations and take protective measures. Report anything that could cause personal injury or device damage to a project supervisor.
- Do not move devices or install racks and power cables in hazardous weather conditions.

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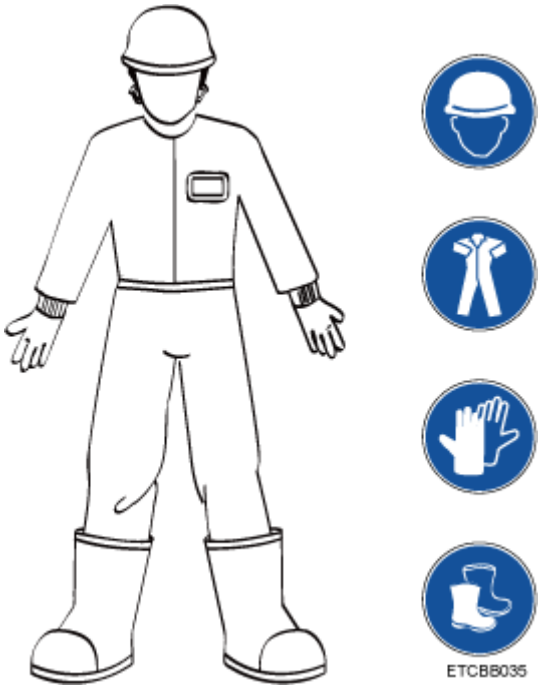
- Do not carry the weight that is over the maximum load per person allowed by local laws or regulations. Before moving or installing equipment, check the maximum equipment weight and arrange required personnel.
- Wear clean protective gloves, ESD clothing, a protective hat, and protective shoes, as shown in **Figure 8-1**.

Figure 8-1 Safety work wear



- Before touching a device, wear ESD clothing and gloves (or wrist strap), and remove any conductive objects (such as watches and jewelry). **Figure 8-2** shows conductive objects that must be removed before you touch a device.

Figure 8-2 Removing conductive objects

Figure 8-3 shows how to wear an ESD wrist strap.

a. Put your hands into the ESD wrist strap.
b. Tighten the strap buckle and ensure that the ESD wrist strap is in contact with your skin.
c. Insert the ground terminal attached to the ESD wrist strap into the jack on the grounded rack or chassis.

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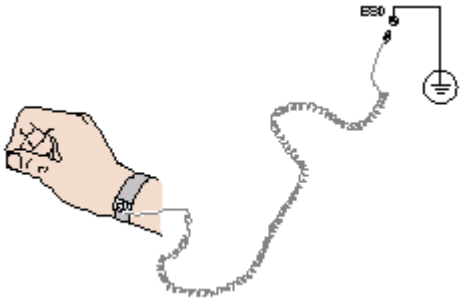
Figure 8-3 Wearing an ESD wrist strap



- Exercise caution when using tools.
- If the installation position of the device is higher than the shoulders of the installation personnel, use a vehicle such as a lift to facilitate installation. Prevent the equipment from falling down and causing personal injury or damage to the equipment.
- The equipment is powered by high-voltage power sources. Direct or indirect contact (especially through damp objects) with high-voltage power sources may result in serious injury or death.
- Ground the equipment before powering it on. Otherwise, personal injury may be caused by high electricity leakage.
- When a ladder is used, ensure that another person holds the ladder steady to prevent accidents.
- When connecting, testing, or replacing an optical cable, do not look into the optical port without eye protection.

Equipment Safety

- Use the recommended power cables at all times.
- Use power cables only for dedicated servers. Do not use them for other devices.
- Before operating equipment, wear ESD clothes and gloves to prevent electrostatic-sensitive devices from being damaged by ESD.
- When moving a device, hold the bottom of the device. Do not hold the handles of the installed modules, such as the PSUs, fan modules, drives, and the mainboard. Handle the equipment with care.
- Exercise caution when using tools that could cause personal injury.
- If the device is configured with active and standby PSUs, connect power cables of active and standby PSUs to different power distribution units (PDUs) to ensure reliable system operating.
- Ground the equipment before powering it on.

Transportation Precautions

Improper transportation may damage equipment. Contact the manufacturer for precautions before attempting transportation.

Transportation precautions include but are not limited to:

- The logistics company engaged to transport the device must be reliable and comply with international standards for transporting electronics. Ensure that the

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equipment being transported is always kept upright. Take necessary precautions to prevent collisions, corrosion, package damage, damp conditions and pollution.

- Transport the equipment in its original packaging.
- If the original packaging is unavailable, package heavy, bulky parts (such as chassis and blades) and fragile parts (such as PCIe GPUs and SSDs) separately.

  NOTE

  Use **Compatibility List** to obtain information abut the components supported by a node or server.
- Power off all devices before transportation.

Maximum Weight Carried by a Person

CAUTION

To reduce the risk of personal injury, comply with local regulations with regard to the maximum weight one person is permitted to carry.

Table 8-1 lists the maximum weight one person is permitted to carry as stipulated by a number of organizations.

Table 8-1 Maximum weight carried per person

Organization	Weight (kg/lb)
European Committee for Standardization (CEN)	25/55.13
International Organization for Standardization (ISO)	25/55.13
National Institute for Occupational Safety and Health (NIOSH)	23/50.72
Health and Safety Executive (HSE)	25/55.13

For more information about safety instructions, see **Server Safety Information**.

8.2 Maintenance and Warranty

For details about the maintenance policy, visit **Customer Support Service**.

For details about the warranty policy, visit **Warranty**.

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9 System Management

The server uses the next-generation Intelligent Baseboard Management Controller (iBMC) to implement remote server management. The iBMC complies with IPMI 2.0 and provides highly reliable hardware monitoring and management.

Features

The iBMC supports the following features and protocols:

- KVM and text console redirection
- Remote virtual media
- IPMI
- SNMP
- Common information model (CIM)
- Redfish
- Browser-based login

Specifications

Table 9-1 iBMC specifications

Specifications	Description
Management interface	Integrates with any standard management system through the following interfaces: ● IPMI ● CLI ● HTTPS ● SNMP ● Redfish
Fault Detection	Detects and accurately locates faults in a field replaceable unit (FRU).

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Specifications	Description
System watchdog	Supports BIOS POST, OS watchdog, and automatic system reset after fault timeout. Users can enable or disable these features individually.
Setting of boot device	Supports out-of-band configuration for the boot device.
Alarm management	Supports alarm management and reports alarms using the SNMP trap, SMTP, and syslog service to ensure 24/7 operating.
Integrated virtual KVM	Provides remote maintenance measures and VNC service for troubleshooting.
Integrated virtual media	Virtualizes local media devices, images, USB keys, and folders into media devices on a remote server, simplifying OS installation. (The virtual DVD-ROM drive supports a maximum transmission rate of 8 MB/s.)
WebUI	Provides a user-friendly graphical user interface (GUI), which simplifies users' configuration and query operations.
Fault reproduction	Reproduces faults to facilitate fault diagnosis.
Screen snapshots and videos	Allows users to view screenshots and videos without login, facilitating routine preventive maintenance inspection (PMI).
Black Box	Allows users to enable or disable the black box function and download black box data.
DNS/LDAP	Supports domain management and directory services, which significantly simplify network and configuration management.
Dual-image backup	Allows a boot from the backup image when the active software crashes.
Device asset management	Provides intelligent asset management, supporting unified management and stocktaking of assets in use.
Intelligent power management	Uses the power capping technology to increase deployment density, and uses dynamic energy saving to lower operating expenses.
IPv6	Supports IPv6 to help build an all-IPv6 environment.
Network Controller Sideband Interface (NC-SI)	Supports NC-SI, allowing access to the iBMC through the service network port.

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10 Certifications

Country/Region	Certification	Standards
Europe	WEEE	2012/19/EU
Europe	REACH	EC NO. 1907/2006
Europe	CE	Safety: EN 62368-1:2014+A11:2017 EMC: EN 55032:2015+A11:2020 CISPR 32:2015+A1:2019 EN IEC 61000-3-2:2019+A1:2021 EN 61000-3-3:2013+A1:2019 EN 55035:2017+A11:2020 CISPR 35:2016 EN 55024:2010+A1:2015 CISPR 24:2010+A1:2015 ETSI EN 300 386 V1.6.1:2012 ETSI EN 300 386 V2.1.1:2016 RoHS: EN IEC 63000:2018 ErP: Commission Regulation(EU) 424/2019

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Country/Region	Certification	Standards
UK	UKCA	Safety: EN 62368-1:2014+A11:2017 EMC: EN 55032:2015+A11:2020 CISPR 32:2015+A1:2019 EN IEC 61000-3-2:2019+A1:2021 EN 61000-3-3:2013+A1:2019 EN 55035:2017+A11:2020 CISPR 35:2016 EN 55024:2010+A1:2015 CISPR 24:2010+A1:2015 ETSI EN 300 386 V1.6.1:2012 ETSI EN 300 386 V2.1.1:2016 RoHS: BS EN IEC 63000:2018 ErP: Commission Regulation(EU) 424/2019
US	FCC	FCC PART 15
Canada	IC	ICES-003
China	CCC	GB 17625.1-2022 GB 4943.1-2022 GB/T 9254.1-2021 (Class A)
China	RoHS	SJ/T-11364 GB/T 26572
Japan	VCCI	VCCI 32-1
Global	CB	IEC 62368-1:2014

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11 Waste Product Recycling

If product users need product recycling service provided by xFusion after products are scrapped, contact technical support for services.

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A Appendix

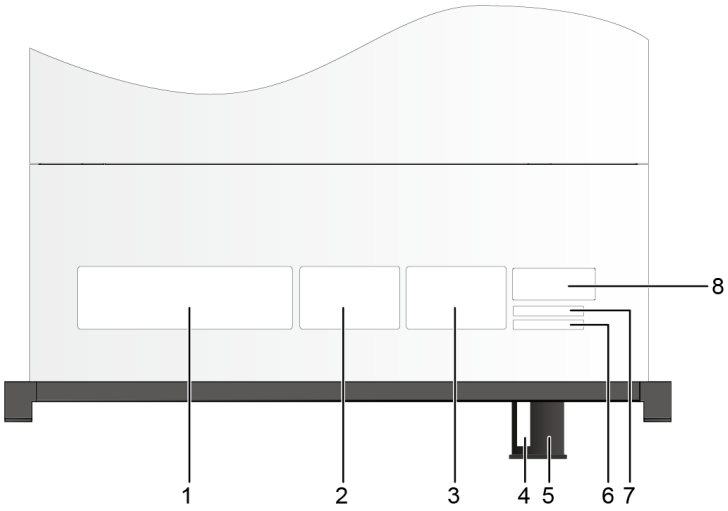
A.1 Chassis Label

NOTE

The label information and location are for reference only. For details, see the actual product.

A.1.1 On the Front Top

Figure A-1 Chassis head label



1	Nameplate	2	Certificate
3	Quick access tag	4	SN **NOTE** For details, see **A.2 Product SN**.

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5	Slide-out label plate **NOTE** The label locations vary with server models or configurations. For details, see **5.1.1 Appearance**.	6	SN **NOTE** For details, see **A.2 Product SN**.
7	Reserved space for custom label	8	Pressure-proof label **NOTE** This label indicates that do not place any objects on top of a rack-mounted device.

A.1.1.1 Nameplate

Figure A-2 Nameplate example

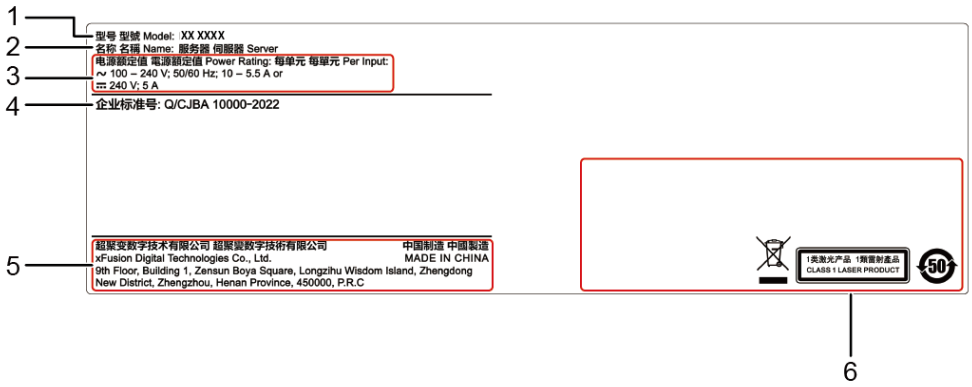

Table A-1 Nameplate description

No.	Description
1	Server Model For details, see **A.4 Nameplate** .
2	Device names
3	Power Supply Requirements
4	Enterprise Standard No.
5	Vendor Information
6	Authentication ID

A.1.1.2 Certificate

Figure A-3 Sample certificate

Table A-2 Certificate description

No.	Description
1	Order
2	No. **NOTE** For details, see **Figure A-4** and **Table A-3**.
3	QC inspector
4	Production date
5	No. Barcode

Figure A-4 Sample certificate No.

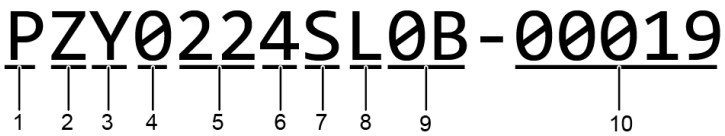

Table A-3 Certificate No. Description

No.	Description
1	The value for this digit is **P**, which is fixed.
2	The value for this digit is **Z**, which is fixed.
3	• **Y**: indicates a server. • **B**: indicates a semi-finished server. • **N**: indicates a spare part.

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No.	Description
4	The value is **0**. This digit is a reserved digit.
5	Indicates the year (two digits).
6	Indicates the month (one digit). ● Digits 1 to 9 indicate January to September, respectively. ● Letters A to C indicate October to December, respectively.
7	Indicates the day (one digit). ● Digits 1 to 9 indicate the 1st to 9th ● Letters A to H indicate the 10th to 17th. ● Letters J to N indicate the 18th to 22nd. ● Letters P to Y indicate the 23rd to 31st
8	Indicates the hour (one digit). ● Digits 0 to 9 indicate 0:00 to 9:00. ● Letters A to H indicate 10:00 to 17:00. ● Letters J to N indicate 18:00 to 22:00. ● Letters P to Q indicate 23:00 to 24:00.
9	Indicates the serial number (two digits).
10	Indicates the manufacturing serial number (five digits).

A.1.1.3 Sample Quick Access Tags

Figure A-5 Sample quick access tags

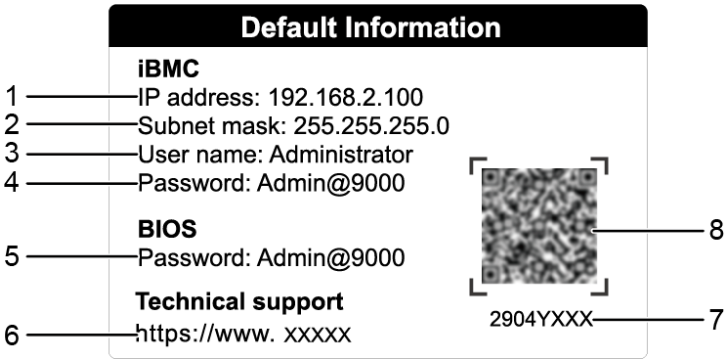

Table A-4 Quick access tab description

No.	Description
1	IP address of the iBMC management network port
2	Subnet mask of the iBMC management network port

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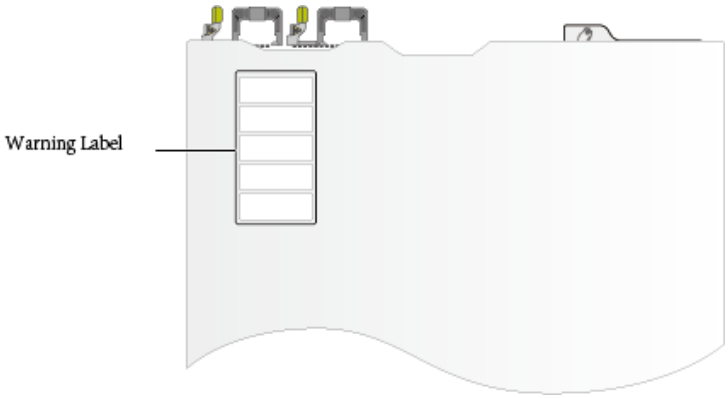
No.	Description
3	Default iBMC user name
4	Default iBMC password
5	Default BIOS password
6	Technical support website
7	P/N Code
8	QR Code **NOTE** Scan the QR code to obtain technical support resources.

A.1.2 Chassis Tail Label

Figure A-6 Chassis tail label

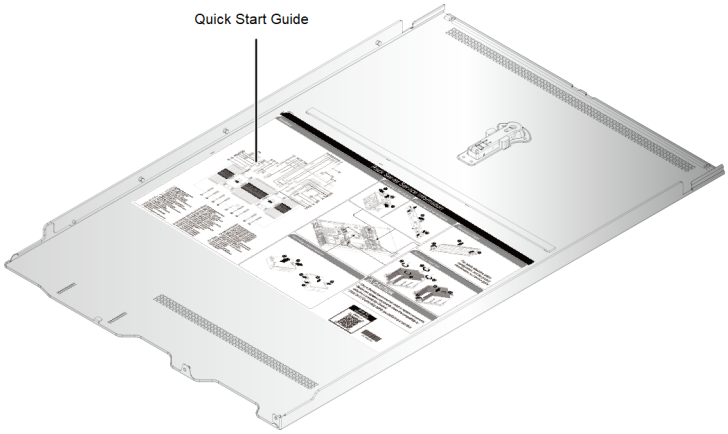


NOTE

For details about the warning label, see **Server Safety Information**.

A.1.3 Chassis Internal Label

Figure A-7 Chassis internal label



NOTE

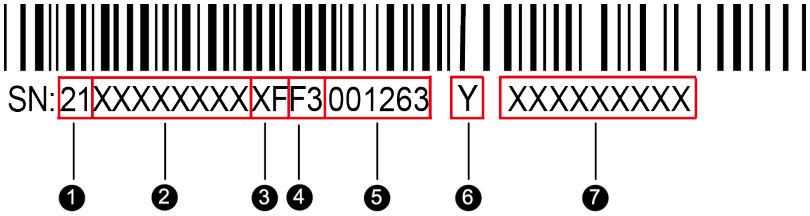
- The quick guide is located on the inside of the chassis cover. It describes how to remove the mainboard components, important components of the chassis, precautions, and QR codes of technical resources. The pictures are for reference only. For details, see the actual product.
- The quick guide is optional. For details, see the actual product.

A.2 Product SN

The serial number (SN) on the slide-out label plate uniquely identifies a device. The SN is required when you contact technical support. **Figure A-8** and **Figure A-9** show the SN formats.

- SN example 1

Figure A-8 SN example 1



- SN example 2

Figure A-9 SN example 2

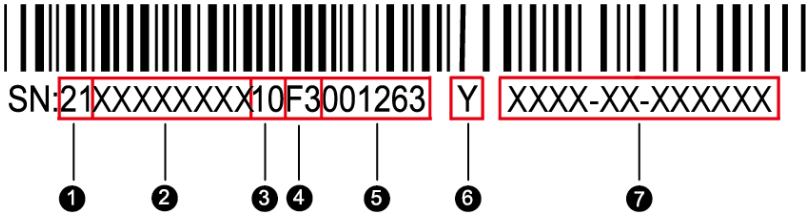


Table A-5 SN example description

No.	Description
1	ESN ID (two characters), which can only be **21**.
2	Material ID (eight characters), that is, the processing code.
3	Vendor code (two characters), that is, the code of the processing place.

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No.	Description
4	Year and month (two characters). ● The first character indicates the year. – Digits 1 to 9 indicate years 2001 to 2009, respectively. – Letters A to H indicate years 2010 to 2017, respectively. – Letters J to N indicate years 2018 to 2022, respectively. – Letters P to Y indicate years 2023 to 2032, respectively. **NOTE** The years from 2010 are represented by upper-case letters excluding I, O, and Z because the three letters are similar to the digits 1, 0, and 2. ● The second character indicates the month. – Digits 1 to 9 indicate January to September, respectively. – Letters A to C indicate October to December, respectively.
5	Serial number (six digits).
6	RoHS compliance (one character). **Y** indicates RoHS compliant.
7	Internal model (product name) of the board. The model format varies according to the actual situation.

A.3 Operating Temperature Limitations

Table A-6 Operating temperature limitations

Configuration	Max. 30°C (86°F)	Max. 35°C (95°F)
24 x 3.5" drive configuration	● All options supported	● All options supported

A.4 Nameplate

Certified Model	Usage Restrictions
H22S-05	Global
2298 V5	Global
Note: The nameplate depends on the actual product.	

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A.5 RAS Features

The server supports a variety of Reliability, Availability, and Serviceability (RAS) features. You can configure these features for better performance.

For details about how to configure these features, see the **Server Purley Platform BIOS Parameter Reference**.

Table A-7 Supported RAS features

Module	Feature	Description
CPU	Corrected Machine Check Interrupt (CMCI)	Corrects error-triggered interrupts.
Memory	Failed DIMM Isolation	Identifies faulty DIMMs to facilitate isolation and replacement of the faulty DIMMs.
	Memory Thermal Throttling	Automatically adjusts the memory temperature to prevent the memory from being damaged due to overheat.
	Rank Sparing	Uses some memory ranks for backup to prevent the system from breaking down due to uncorrectable errors.
	Memory Address Parity Protection	Detects memory command and address errors.
	Memory Demand and Patrol Scrubbing	Corrects correctable errors upon detection. If these errors are not corrected in a timely manner, uncorrectable errors may occur.
	Memory Mirroring	Provides high reliability for the system via mirroring.
	Single Device Data Correction (SDDC)	Corrects single-chip multi-bit errors to improve memory reliability.
	Device Tagging	Degrades and rectifies memory faults to improve memory availability.
	Data Scrambling	Optimizes data flow distribution to reduce the error probability and improve memory data flow reliability and address error detection.
PCIe	PCIe Advanced Error Reporting	Provides a PCIe advanced error reporting mechanism to improve server serviceability.
UPI	Intel UPI Link Level Retry	Provides a retry mechanism to improve the reliability of UPI links.

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Module	Feature	Description
	Intel UPI Protocol Protection via CRC	Provides cyclic redundancy check (CRC) protection for UPI data packets to improve system reliability.
System	Core Disable For FRB (Fault Resilient Boot)	Isolates a faulty CPU core during startup to improve system reliability and availability.
	Corrupt Data Containment Mode	Marks the memory storage unit when a data error occurs to limit the impact on the running program and improve system reliability.
	Socket disable for FRB (Fault Resilient Boot)	Isolates a faulty socket during the BIOS startup process to improve system reliability.
	Architected Error Records	With the features such as eMCA, the BIOS collects error information recorded in hardware registers in compliance with UEFI specifications, notifies the OS through the APEI interface of the ACPI, and locates the error unit, improving system availability.
	Error Injection Support	Implements fault injection to verify RAS features.
	Machine Check Architecture (MCA)	Provides a software repair function to rectify uncorrectable errors to improve system availability.
	Enhanced Machine Check Architecture (eMCA): Gen2	Improves system availability.
	OOB access to MCA registers	The out-of-band system can access MCA registers through the PECI. When a fatal error occurs in the system, the out-of-band system can collect onsite data to facilitate subsequent fault analysis and locating and improve system serviceability.
	BIOS Abstraction Layer for Error Handling	The BIOS processes errors and reports error information to the OS based on specifications, improving system serviceability.
	BIOS-based Predictive Failure Analysis (PFA)	The OS takes the lead. The BIOS provides information about physical memory error units. The OS tracks, predicts, and handles the errors.

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A.6 Sensor List

Sensor	Description	Component
Inlet Temp	Air inlet temperature	Left mounting ear
Outlet Temp	Air outlet temperature	Mainboard
PCH Temp	PCH bridge temperature	Mainboard
CPU*N* Core Rem	CPU core temperature	CPU*N* *N* indicates the CPU number. The value is **1** or **2**.
CPU*N* DTS	CPU DTS value	CPU*N* *N* indicates the CPU number. The value is **1** or **2**.
CPU*N* Margin	CPU Margin	CPU*N* *N* indicates the CPU number. The value is **1** or **2**.
CPU*N* VDDQ Temp	CPU VDDQ temperature	Mainboard *N* indicates the CPU number. The value is **1** or **2**.
CPU*N* VRD Temp	CPU VRD temperature	Mainboard *N* indicates the CPU number. The value is **1** or **2**.
CPU*N* MEM Temp	CPU DIMM temperature	DIMMs of CPU*N* *N* indicates the CPU number. The value is **1** or **2**.
SYS 3.3V	Mainboard 3.3 V voltage	Mainboard
SYS 5V	Mainboard 5.0 V voltage	Mainboard
SYS 12V_1	Mainboard 12.0 V voltage	Mainboard
SYS 12V_2	Mainboard 12.0 V voltage	Mainboard
CPU*N* VCore	1.8 V CPU voltage	Mainboard *N* indicates the CPU number. The value is **1** or **2**.

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Sensor	Description	Component
CPU*N* DDR VDDQ	1.2 V DIMM voltage	Mainboard *N* indicates the CPU number. The value is **1** or **2**.
CPU*N* DDR VDDQ2	1.2 V DIMM voltage	Mainboard *N* indicates the CPU number. The value is **1** or **2**.
CPU*N* VSA	CPU VSA voltage	Mainboard *N* indicates the CPU number. The value is **1** or **2**.
CPU*N* VCCIO	CPU VCCIO voltage	Mainboard *N* indicates the CPU number. The value is **1** or **2**.
CPU*N* VMCP	CPU VMCP voltage	Mainboard *N* indicates the CPU number. The value is **1** or **2**.
PCH VPVNN	PCH VPVNN voltage	Mainboard
PCH PRIM 1V05	PCH PRIM voltage	Mainboard
HDD BP*N* STBY3.3V	Drive backplane 3.3 V voltage	Front-drive backplane *N* indicates the backplane number. The value is **1** or **2**.
HDD BP*N* 5V	Drive backplane 5.0 V voltage	Front-drive backplane *N* indicates the backplane number. The value is **1** or **2**.
HDD BP*N* 12V	Drive backplane 12.0 V voltage	Front-drive backplane *N* indicates the backplane number. The value is **1** or **2**.
CPU*N* VCCP	CPU VCCP voltage	Mainboard
CPU*N* DDR VPP1	CPU DDR voltage	Mainboard
CPU*N* DDR VPP2	CPU DDR voltage	Mainboard

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Sensor	Description	Component
FAN*N* Speed	Fan speed	Fan module*N* *N* indicates the fan module number. The value ranges from **1** to **5**.
Power	Server input power	PSUs
PS*N* VIN	Input voltage of PSU*N*	PSU*N* *N* indicates the PSU number. The value is **1** or **2**.
Disks Temp	Maximum temperature of SAS/SATA drives	SAS/SATA drives
Power*N*	PSU input power	PSU*N* *N* indicates the PSU number. The value is **1** or **2**.
PCH Status	PCH chip fault diagnosis health status	Mainboard
CPU*N* QPI Link	CPU QPI link fault diagnosis health status	Mainboard or CPU*N* *N* indicates the CPU number. The value is **1** or **2**.
CPU*N* Prochot	CPU Prochot	CPU*N* *N* indicates the CPU number. The value is **1** or **2**.
System Error	System suspension or restart. Check the background logs	Mainboard
CPU*N* Status	CPU status	CPU*N* *N* indicates the CPU number. The value is **1** or **2**.
CPU*N* Memory	CPU memory status	DIMMs of CPU*N* *N* indicates the CPU number. The value is **1** or **2**.
FAN*N* Status	Fan status	Fan module*N* *N* indicates the fan module number. The value ranges from **1** to **5**.

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Sensor	Description	Component
DIMM*N*	DIMM status	DIMM*N* *N* indicates the DIMM slot number.
RTC Battery	RTC battery status. An alarm is generated when the voltage is lower than 1 V.	RTC battery
PCIE Status	PCIe status	PCIe cards
ACPI State	ACPI status	Mainboard
Power Button	Power button pressed state	Mainboard and power button
Watchdog2	Watchdog	Mainboard
Mngmnt Health	Management subsystem health status	Management modules
UID Button	UID button status	Mainboard
PwrOk Sig. Drop	Voltage dip status	Mainboard
PwrOn TimeOut	Power-on timeout	Mainboard
PwrCap Status	Power capping status	Mainboard
HDD Backplane	Entity presence	Drive backplane
HDD BP Status	Drive backplane health status	Drive backplane
Riser1 Card	Entity presence	Riser card
SAS Cable	Entity presence	SAS high-speed cable on the mainboard
FAN*N* Presence	Fan presence	Fan module*N* *N* indicates the fan module number. The value ranges from **1** to **5**.
RAID Presence	RAID controller card presence	RAID controller card
PS Redundant	Redundancy failure due to PSU removal	PSUs
NIC# Status	NIC fault diagnosis health status	LOM

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Sensor	Description	Component
PS*N* Status	PSU status	PSU*N* *N* indicates the PSU number. The value is **1** or **2**.
PS*N* Fan Status	PSU fan status	PSU*N* *N* indicates the PSU number. The value is **1** or **2**.
PS*N* Temp Status	PSU presence	PSU*N* *N* indicates the PSU number. The value is **1** or **2**.
DISK*N*	Drive status	Drive*N* *N* indicates the drive slot number. The value ranges from **0** to **27**.
M2Disk*N*	Status of the M.2 drives on the riser card	M.2 drives on the riser card
Port*N* Link Down	LOM	LOM
PCIe RAID$ Temp	PCIe RAID controller card temperature	PCIe RAID controller card
RAID Temp	RAID controller card temperature	RAID controller card
RAID Status	RAID controller card health status	RAID controller card
RAID PCIE ERR	RAID controller card fault diagnosis health status	RAID controller card
IB$ TEMP	IB adapter temperature	IB adapter
RAID Card BBU	RAID controller card BBU	BBU supercapacitor of RAID controller card
PS$ Inlet Temp	PSU air inlet temperature	PSUs
OCP1 OP Temp	OCP 2.0 mezzanine card optical module temperature	OCP 2.0 mezzanine card optical module temperature
OCP1 Temp	OCP 2.0 mezzanine card chip temperature	OCP 2.0 mezzanine card chip temperature

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B Glossary

B.1 A-E

E

ejector lever	A part on the panel of a device used to facilitate installation or removal of the device.
Ethernet	A baseband local area network (LAN) architecture developed by Xerox Corporation by partnering with Intel and DEC. Ethernet uses the Carrier Sense Multiple Access/Collision Detection (CSMA/CD) access method and allows data transfer over various cables at 10 Mbit/s. The Ethernet specification is the basis for the IEEE 802.3 standard.

B.2 F-J

G

Gigabit Ethernet (GE)	An extension and enhancement of traditional shared media Ethernet standards. It is compatible with 10M and 100M Ethernet and complies with IEEE 802.3z standards.

H

hot swap	Replacing or adding components without stopping or shutting down the system.

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B.3 K-O

K

KVM	A hardware device that provides public keyboard, video and mouse (KVM).

B.4 P-T

P

panel	An external component (including but not limited to ejector levers, indicators, and ports) on the front or rear of the server. It seals the front and rear of the chassis to ensure optimal ventilation and electromagnetic compatibility (EMC).
Peripheral Component Interconnect Express (PCIe)	A computer bus PCI, which uses the existing PCI programming concepts and communication standards, but builds a faster serial communication system. Intel is the main sponsor for PCIe. PCIe is used only for internal interconnection. A PCI system can be transformed to a PCIe one by modifying the physical layer instead of software. PCIe delivers a faster speed and can replace almost all AGP and PCI buses.

R

redundancy	A mechanism that allows a backup device to automatically take over services from a faulty device to ensure uninterrupted running of the system.
redundant array of independent disks (RAID)	A storage technology that combines multiple physical drives into a logical unit for the purposes of data redundancy and performance improvement.

S

server	A special computer that provides services for clients over a network.
system event log (SEL)	Event records stored in the system used for subsequent fault diagnosis and system recovery.

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B.5 U-Z

U

U	A unit defined in International Electrotechnical Commission (IEC) 60297-1 to measure the height of a cabinet or chassis. 1 U = 44.45 mm
UltraPath Interconnect (UPI)	A point-to-point processor interconnect developed by Intel.

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C Acronyms and Abbreviations

C.1 A-E

A

AC	alternating current
AES	Advanced Encryption Standard New Instruction Set
ARP	Address Resolution Protocol
AVX	Advanced Vector Extensions

B

BBU	backup battery unit
BIOS	Basic Input/Output System

C

CD	calendar day
CE	Conformite Europeenne
CIM	Common Information Model
CLI	command-line interface

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D

DC	direct current
DCPMM	DC persistent memory module
DDR3	Double Data Rate 3
DDR4	Double Data Rate 4
DDDC	double device data correction
DEMT	Dynamic Energy Management Technology
DIMM	dual in-line memory module
DRAM	dynamic random-access memory
DVD	digital video disc

E

ECC	error checking and correcting
ECMA	European Computer Manufacturer Association
EDB	Execute Disable Bit
EN	European Efficiency
ERP	enterprise resource planning
ETS	European Telecommunication Standards

C.2 F-J

F

FB-DIMM	Fully Buffered DIMM
FC	Fiber Channel
FCC	Federal Communications Commission
FCoE	Fibre Channel over Ethernet
FTP	File Transfer Protocol

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G

GE	Gigabit Ethernet
GPIO	General Purpose Input/Output
GPU	graphics processing unit

H

HA	high availability
HDD	hard disk drive
HPC	high-performance computing
HTTP	Hypertext Transfer Protocol
HTTPS	Hypertext Transfer Protocol Secure

I

iBMC	intelligent baseboard management controller
IC	Industry Canada
ICMP	Internet Control Message Protocol
IDC	Internet Data Center
IEC	International Electrotechnical Commission
IEEE	Institute of Electrical and Electronics Engineers
IGMP	Internet Group Message Protocol
IOPS	input/output operations per second
IP	Internet Protocol
IPC	intelligent power capability
IPMB	Intelligent Platform Management Bus
IPMI	Intelligent Platform Management Interface

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C.3 K-O

K

KVM	keyboard, video, and mouse

L

LC	Lucent connector
LRDIMM	load-reduced dual in-line memory module
LED	light emitting diode
LOM	LAN on motherboard

M

MAC	media access control
MMC	module management controller

N

NBD	next business day
NC-SI	Network Controller Sideband Interface

C.4 P-T

P

PCIe	Peripheral Component Interconnect Express
PDU	power distribution unit
PHY	physical layer
PMBUS	power management bus
POK	power OK
PWM	pulse-width modulation

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PXE	Preboot Execution Environment

Q

QPI	Quick Path Interconnect

R

RAID	redundant array of independent disks
RAS	reliability, availability and serviceability
RDIMM	registered dual in-line memory module
REACH	Registration Evaluation and Authorization of Chemicals
RJ45	registered jack 45
RoHS	Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment

S

SAS	Serial Attached Small Computer System Interface
SATA	Serial Advanced Technology Attachment
SCM	supply chain management
SDDC	single device data correction
SERDES	serializer/deserializer
SGMII	serial gigabit media independent interface
SMI	serial management interface
SMTP	Simple Mail Transfer Protocol
SNMP	Simple Network Management Protocol
SOL	serial over LAN
SONCAP	Standards Organization of Nigeria-Conformity Assessment Program
SSD	solid-state drive
SSE	Streaming SIMD Extensions

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T

TACH	tachometer signal
TBT	Turbo Boost Technology
TCG	Trusted Computing Group
TCM	trusted cryptography module
TCO	total cost of ownership
TDP	thermal design power
TELNET	Telecommunication Network Protocol
TET	Trusted Execution Technology
TFM	TransFlash module
TFTP	Trivial File Transfer Protocol
TOE	TCP offload engine
TPM	trusted platform module

C.5 U-Z

U

UDIMM	unbuffered dual in-line memory module
UEFI	Unified Extensible Firmware Interface
UID	unit identification light
UL	Underwriter Laboratories Inc.
USB	Universal Serial Bus

V

VCCI	Voluntary Control Council for Interference by Information Technology Equipment
VGA	Video Graphics Array
VLAN	virtual local area network
VRD	voltage regulator-down

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W

WEEE	waste electrical and electronic equipment
WSMAN	Web Service Management

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